

# Optimization of non-evaporable getter coating for accelerator beam pipe

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# Outlet

- Introduction
- Pumping property
  - Film deposition
  - Surface analysis
  - NEG activation procedure
  - Pumping properties measurements
  - Activation temperature
- Sticking probability and capacity for different NEG coatings
- Desorption properties
  - How to reduce ESD
  - What film is needed
  - What achieved
- Conclusions

## What are usual considerations for vacuum

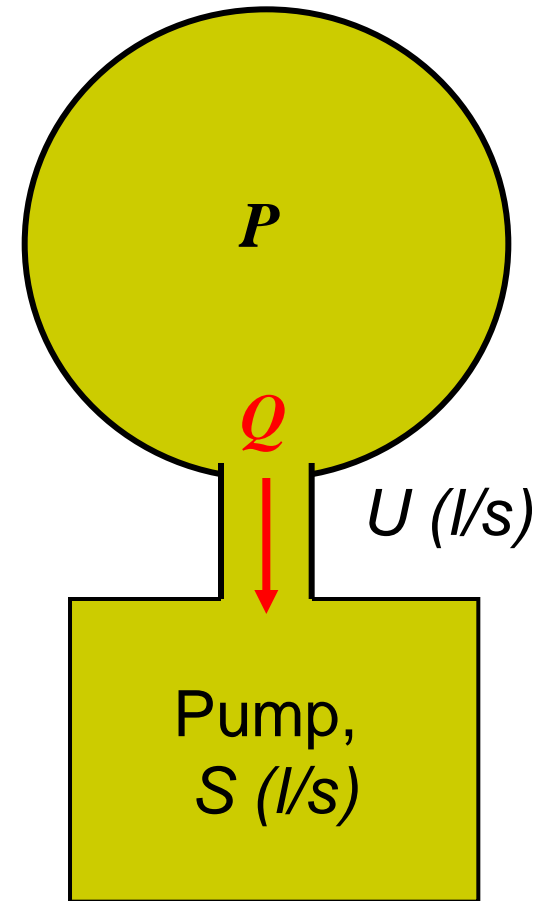
Required pressure  $P$  is defined by gas desorption  $Q$  in the vessel and effective pumping speed  $S_{eff}$

In a simple case it is

$$P = \frac{Q}{S_{eff}} = Q \left( \frac{1}{S} + \frac{1}{U} \right)$$

$$Q = qA + \eta_{\gamma} \Gamma + \eta_e I_e + \eta_{ion} I_{ion}$$

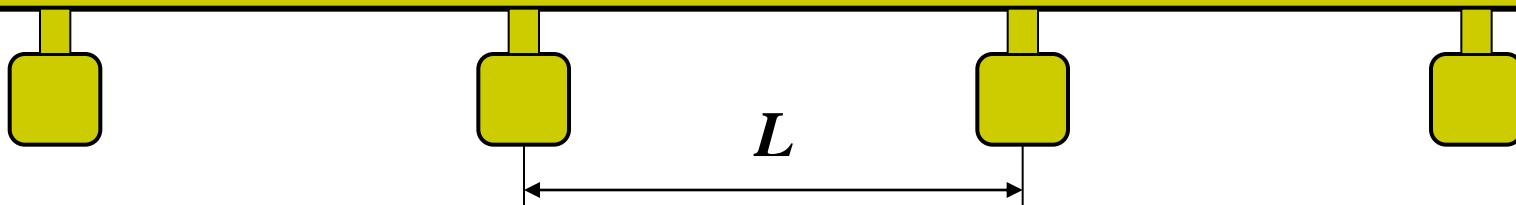
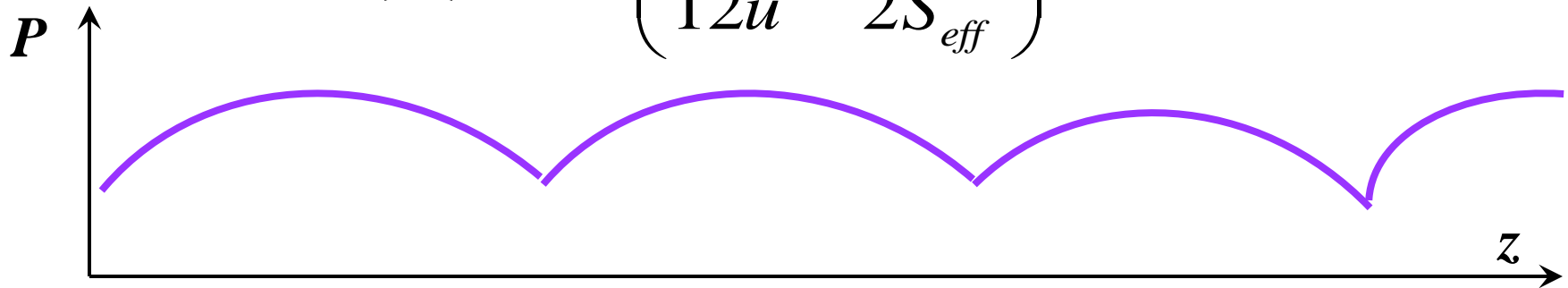
Thermal, photon, electron and ion stimulated desorption



## Usual accelerator vacuum chamber

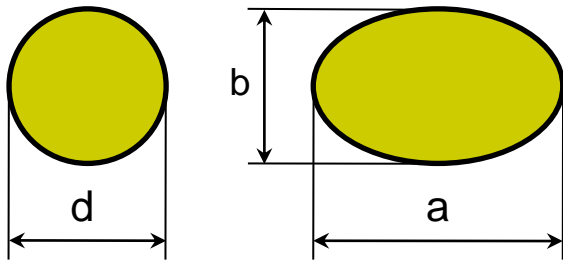
- Long tube with length  $L \gg a$ , where  $a$  - transversal dimension
- Average pressure depends on vacuum conductance  $u(L, a)$  of the beam vacuum chamber

$$\langle P \rangle = qL \left( \frac{L}{12u} + \frac{1}{2S_{eff}} \right) k_B T$$

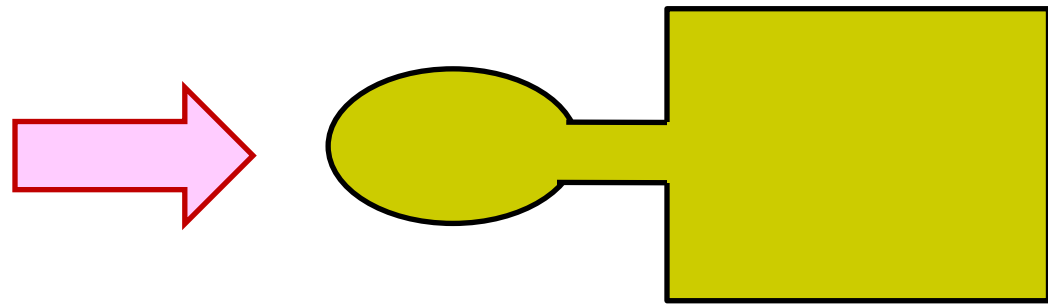


# Vacuum chamber cross sections

Beam pipe  
Circular or elliptical  
 $4 \text{ mm} \leq d, a, b \leq 200 \text{ mm}$

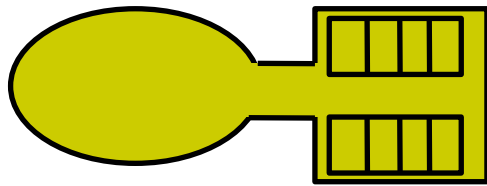


Vacuum chamber with an antechamber  
for larger vacuum conductance,  $U$

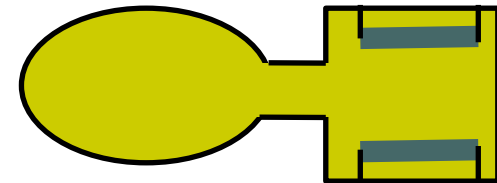
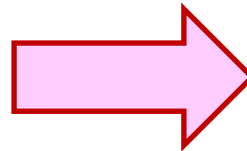


## Distributed pumping

In dipole magnetic field



With NEG strips  
(LEP in CERN)



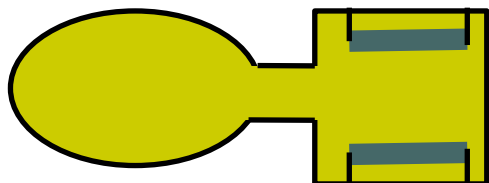
## Two concepts of the ideal vacuum chamber

### Traditional:

- surface which outgasses as little as possible ('nil' ideally)
- surface which **does not pump** otherwise that surface is contaminated over time

### Results in

- Surface cleaning, conditioning, coatings
- Vacuum firing, *ex-situ* baling
- Baking *in-situ* to up to **300°C**
- Separate pumps

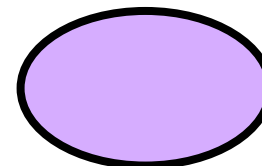


### 'New' (C. Benvenuti, CERN, ~1998):

- surface which outgasses as little as possible ('nil' ideally)
- a surface which **does pump**, however, will not be contaminated due to a very low outgassing rate

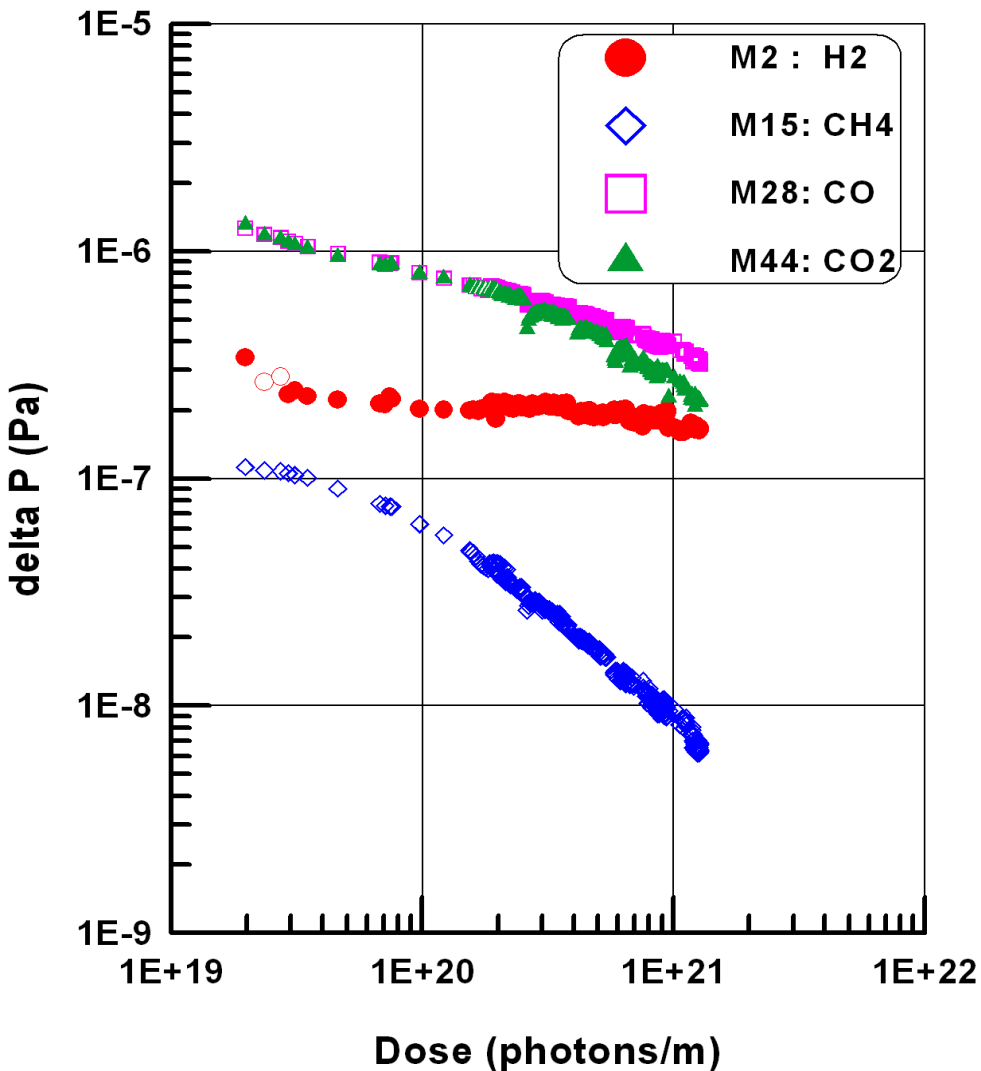
### Results in

- NEG coated surface
- There should be no un-coated parts
- Activating (baking) *in-situ* at **150-180°C**
- Small pumps for  $C_xH_y$  and noble gases

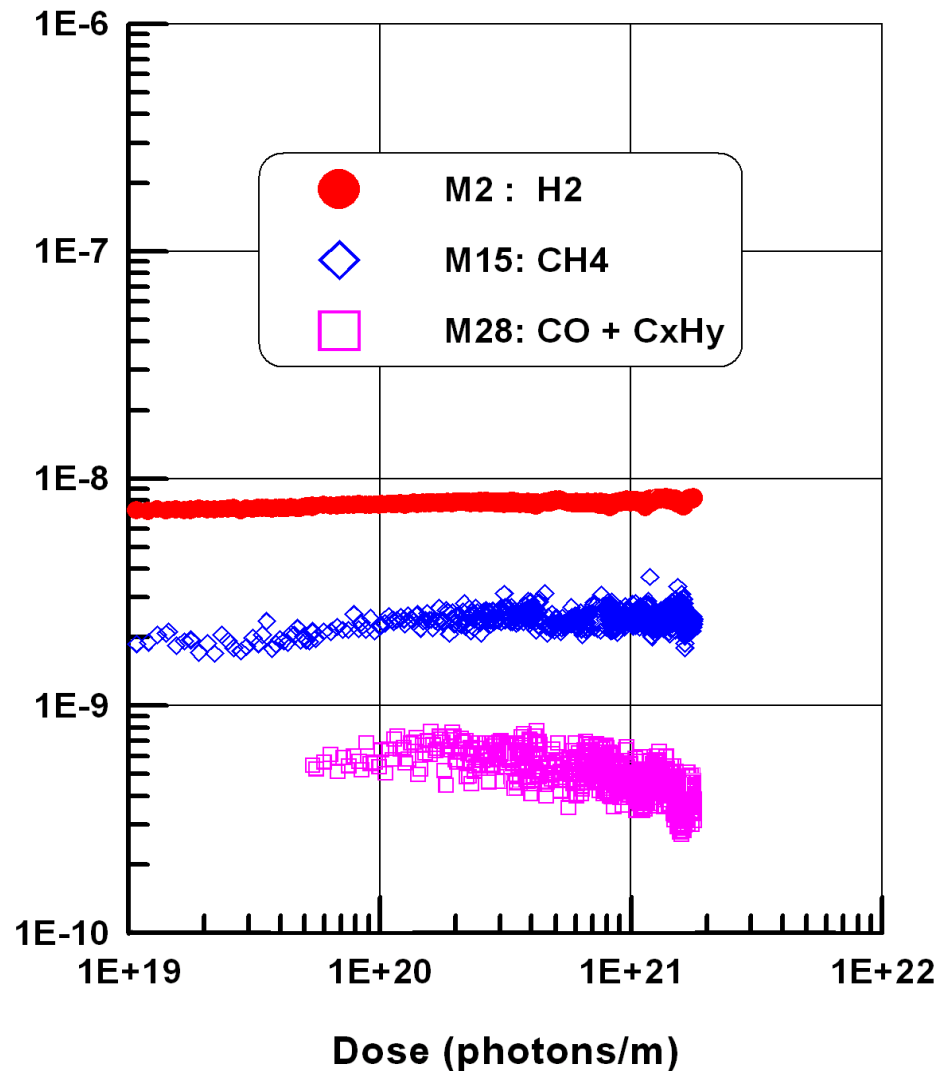


# Stainless steel vs. NEG coated vacuum chamber under SR

## Stainless steel



## TiZrV



V.V. Anashin et al. *Vacuum* 75 (2004), p. 155.

## NEG coating for accelerators

- First used in the ESRF (France);
- ELETTRA (Italy);
- Diamond LS (UK);
- Soleil (France) – first fully NEG coated;
- LHC (Switzerland) – longest NEG coated vacuum chamber;
- SIS-18 (Germany);
- and many others.
- **NEG film capacity for CO and CO<sub>2</sub> is ~1ML:**
  - If  $P = 10^{-9}$  mbar then 1 ML can be sorbed just in  $\sim 10^3 - 10^4$  s;
  - Lab measurements of different NEG coatings often don't repeat CERN's data on sticking probability and capacity;
  - However, NEG coated parts of accelerators work well.



## NEG coating for accelerators (2)

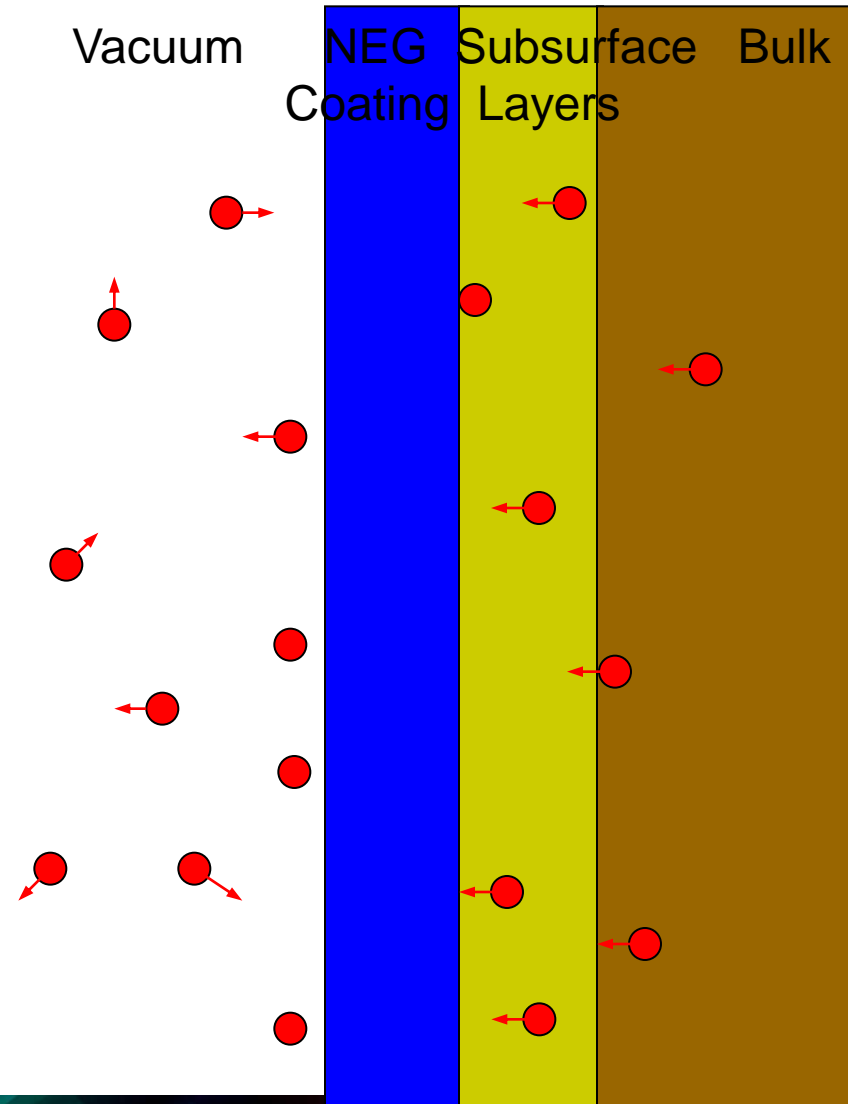
- What is required:
  - Input data for accelerator design:
    - $\eta(D, E, T_a)$ ,  $\alpha(M, T_a)$ , pumping capacity;
  - Better understanding:
    - what and why;
    - practical 'do's and 'don't's';
  - Further development of this coating:
    - lower  $\eta$ ,  $T_a$ , SEY;
    - higher  $\alpha(M)$ , pumping capacity;
    - optimising for an application.

## What NEG coating does

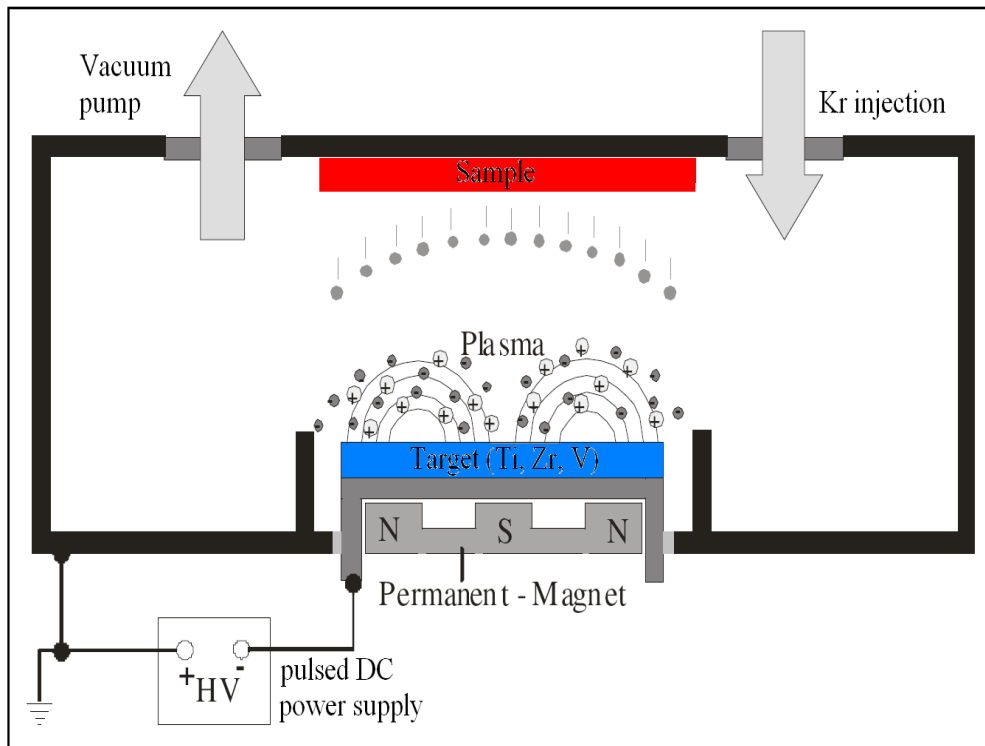
- **Reduces gas desorption:**
  - A pure metal film ~1- $\mu\text{m}$  thick without contaminants.
  - A barrier for molecules from the bulk of vacuum chamber.
- **Increases distributed pumping speed,  $S$ :**
  - A sorbing surface on whole vacuum chamber surface

$$S = \alpha \cdot A \cdot v / 4;$$

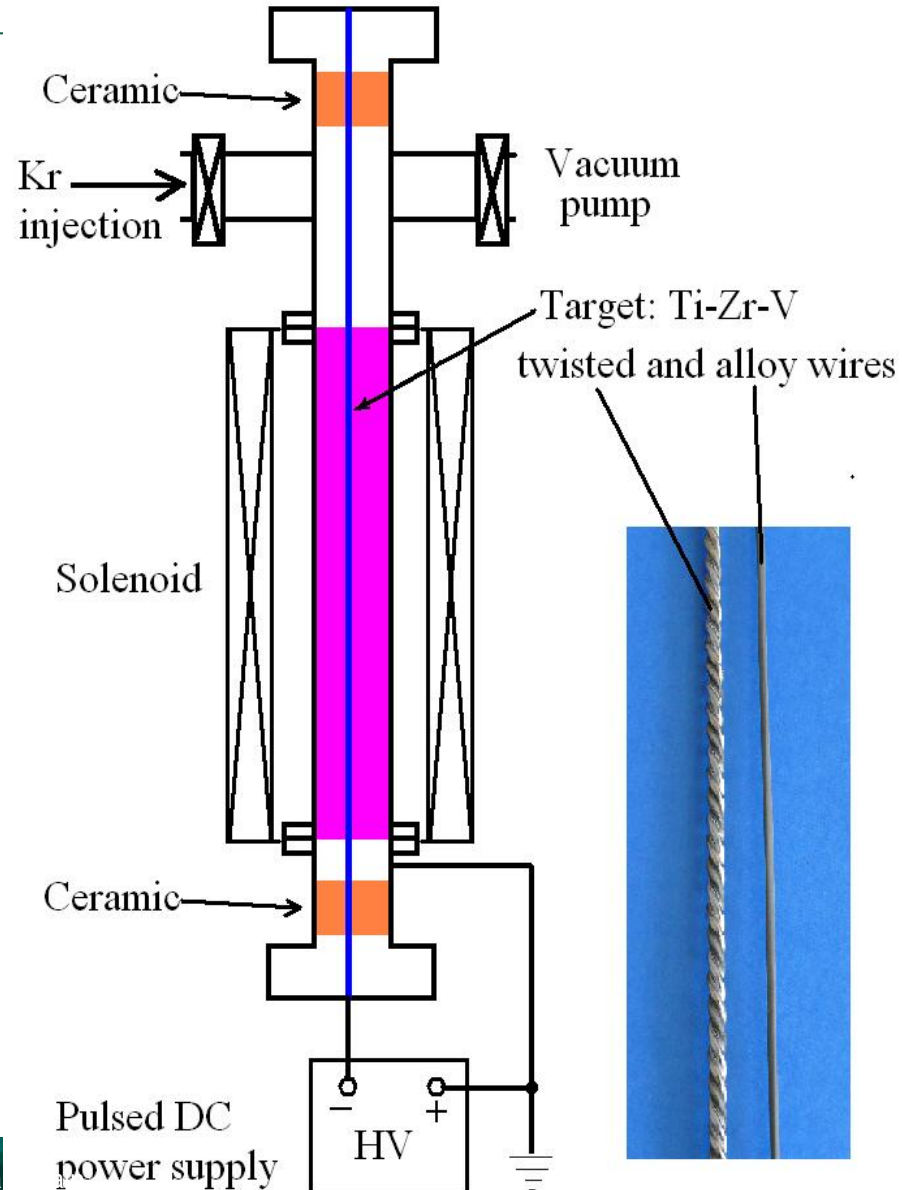
where  $\alpha$  – sticking probability,  
 $A$  – surface area,  
 $v$  – mean molecular velocity



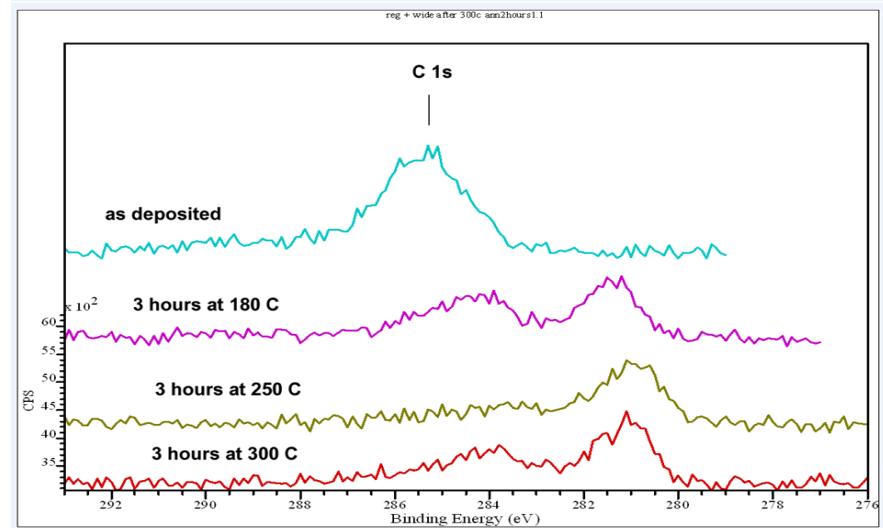
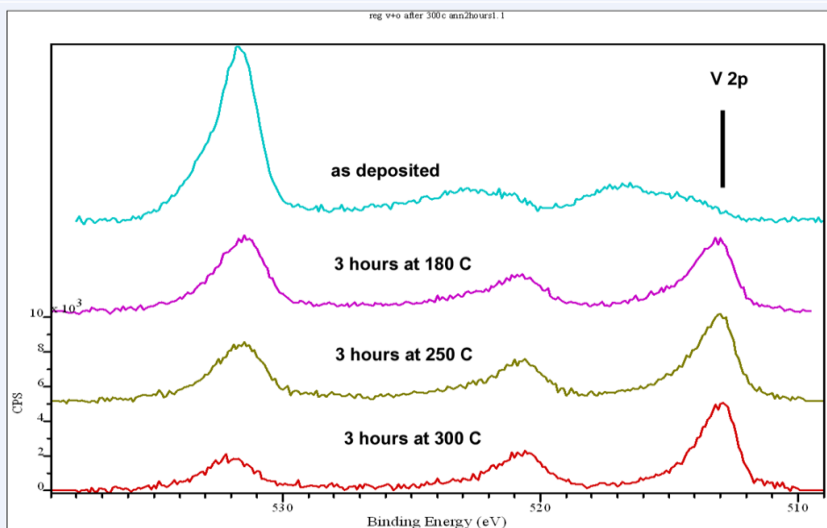
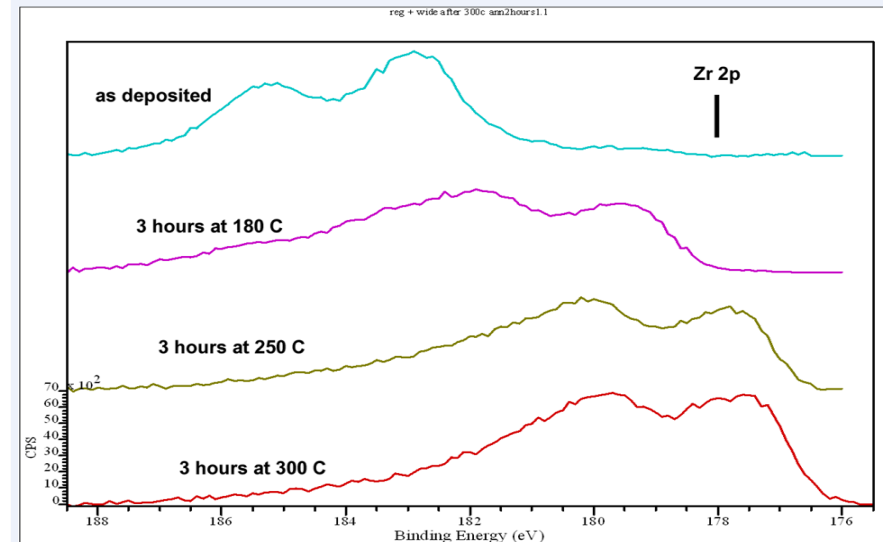
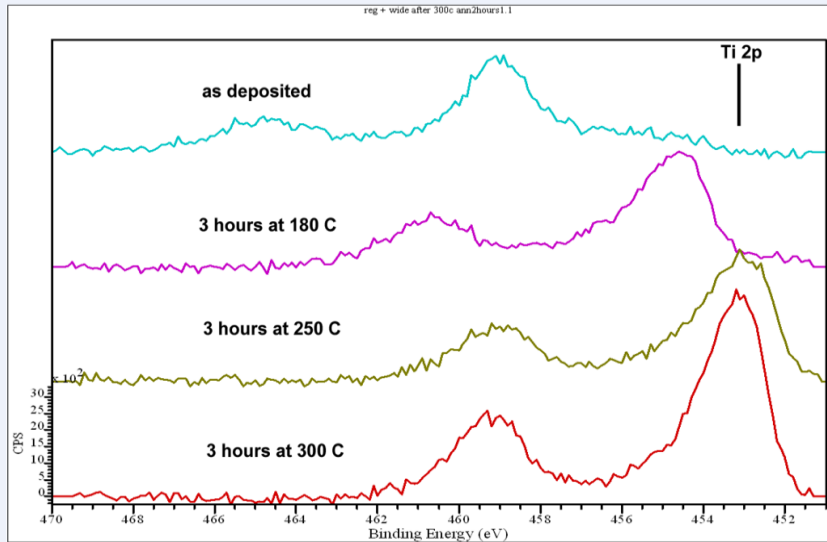
## Planar magnetron deposition



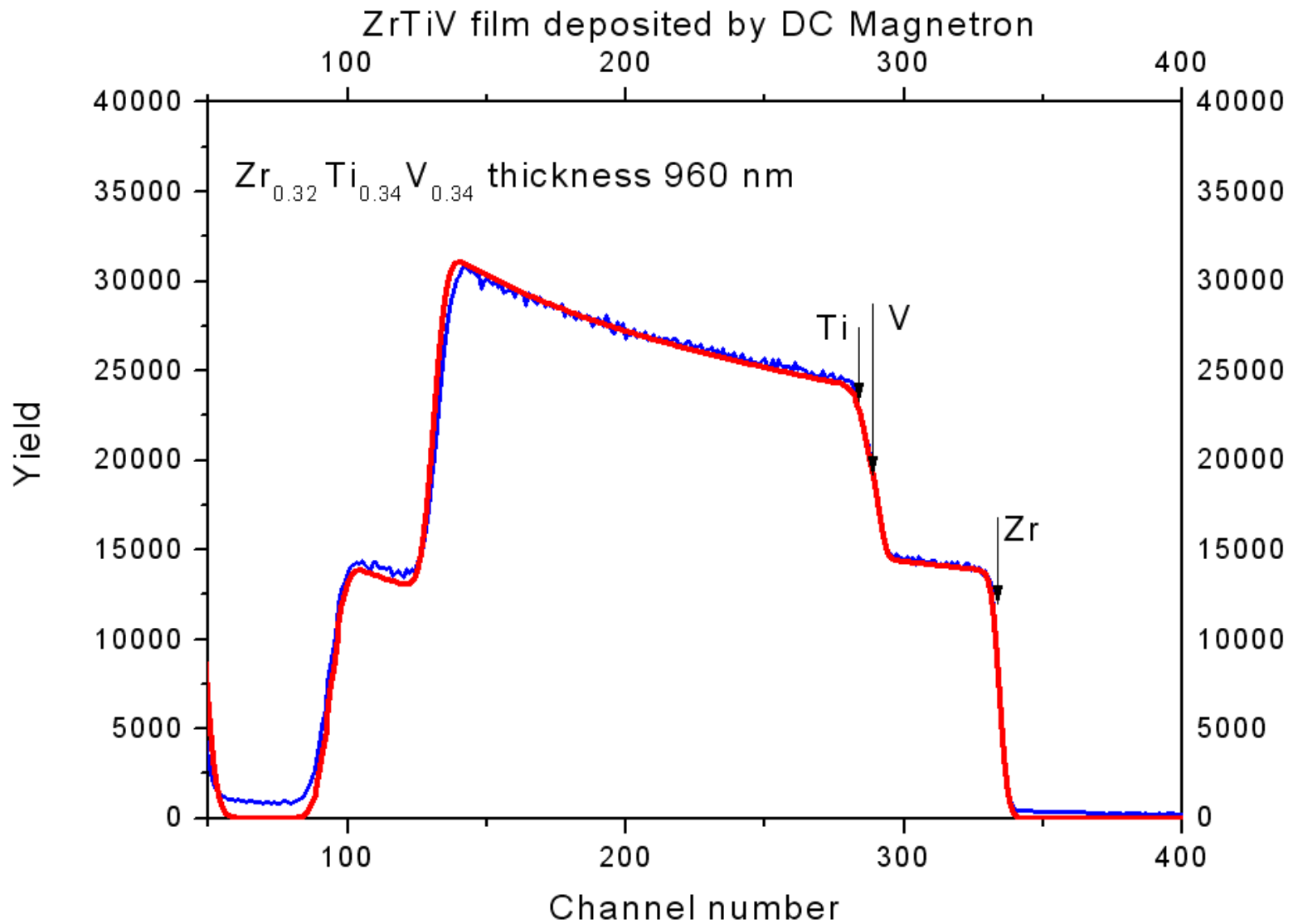
## Cylindrical magnetron deposition



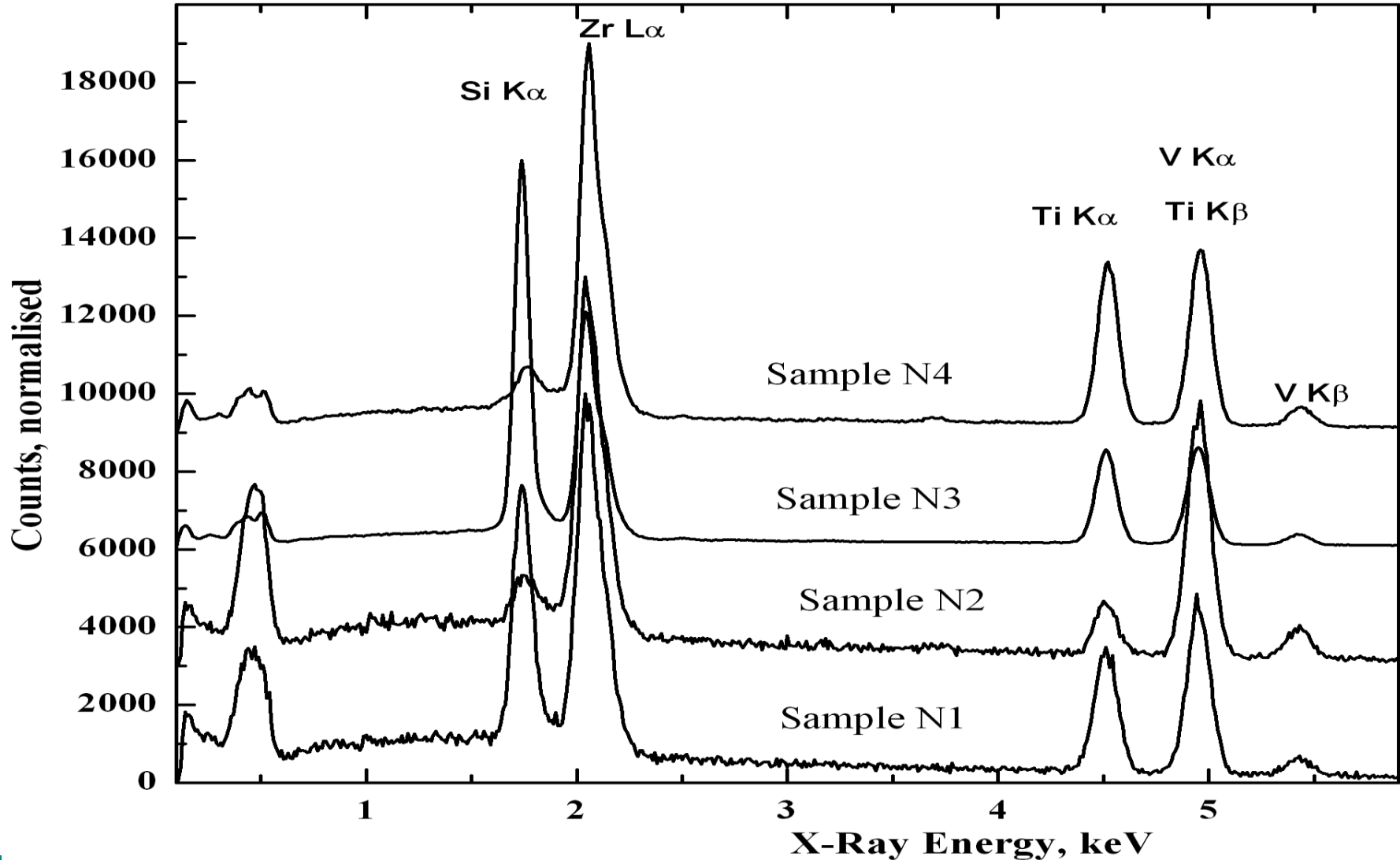
# Region scan of XPS core levels of Ti, Zr, C and V of a Ti-Zr-V film (surface composition and chemical bounding)



# RBS (film compositions in bulk)

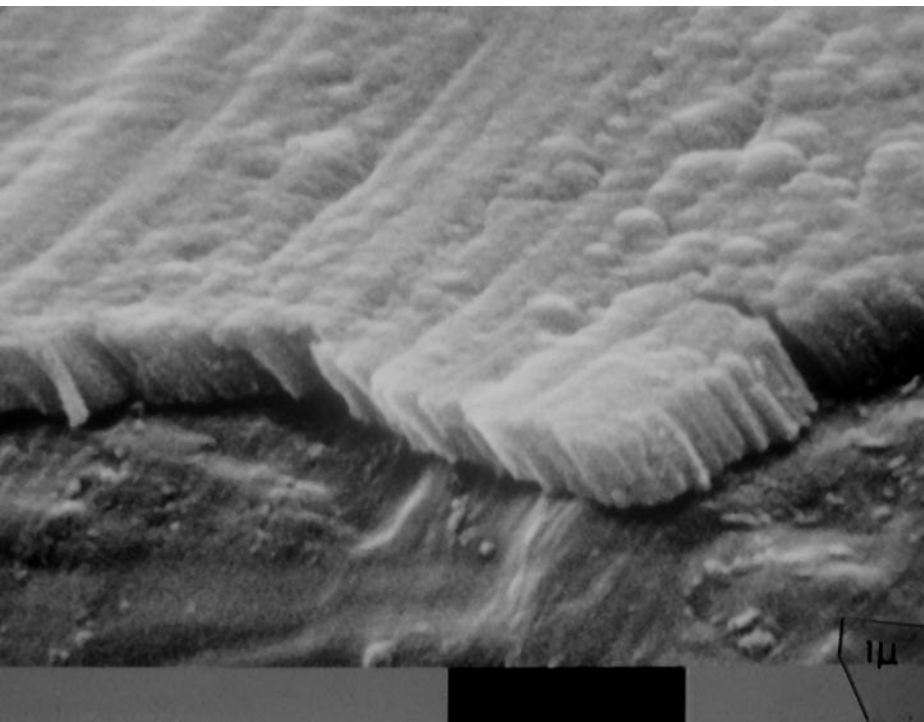


# The EDX analysis for determination of film composition

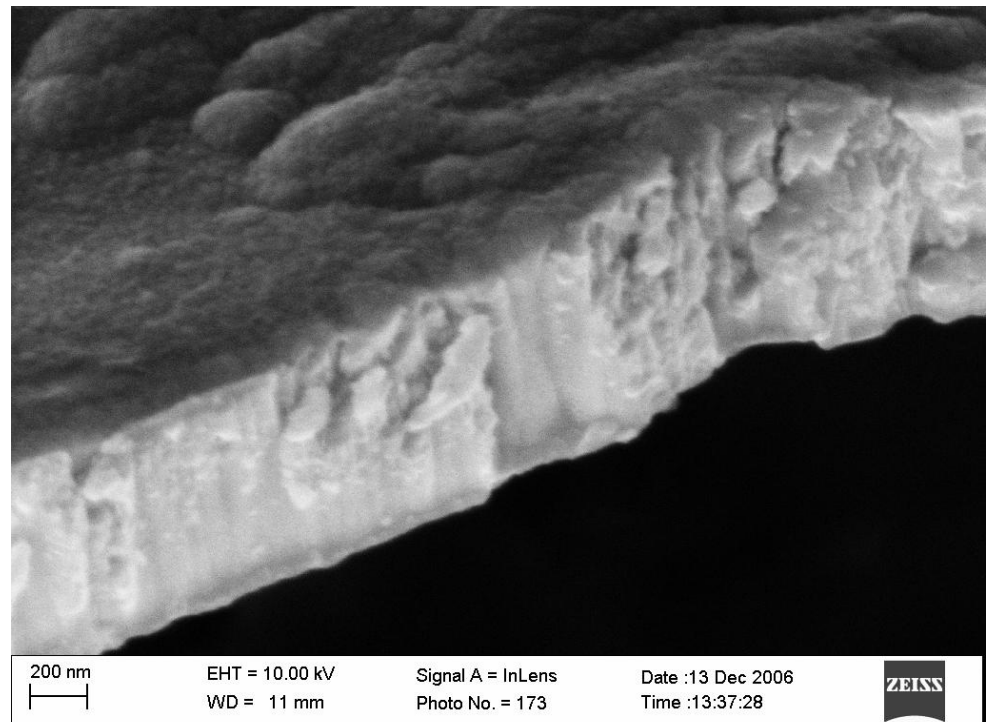


## SEM images of films (film morphology )

columnar

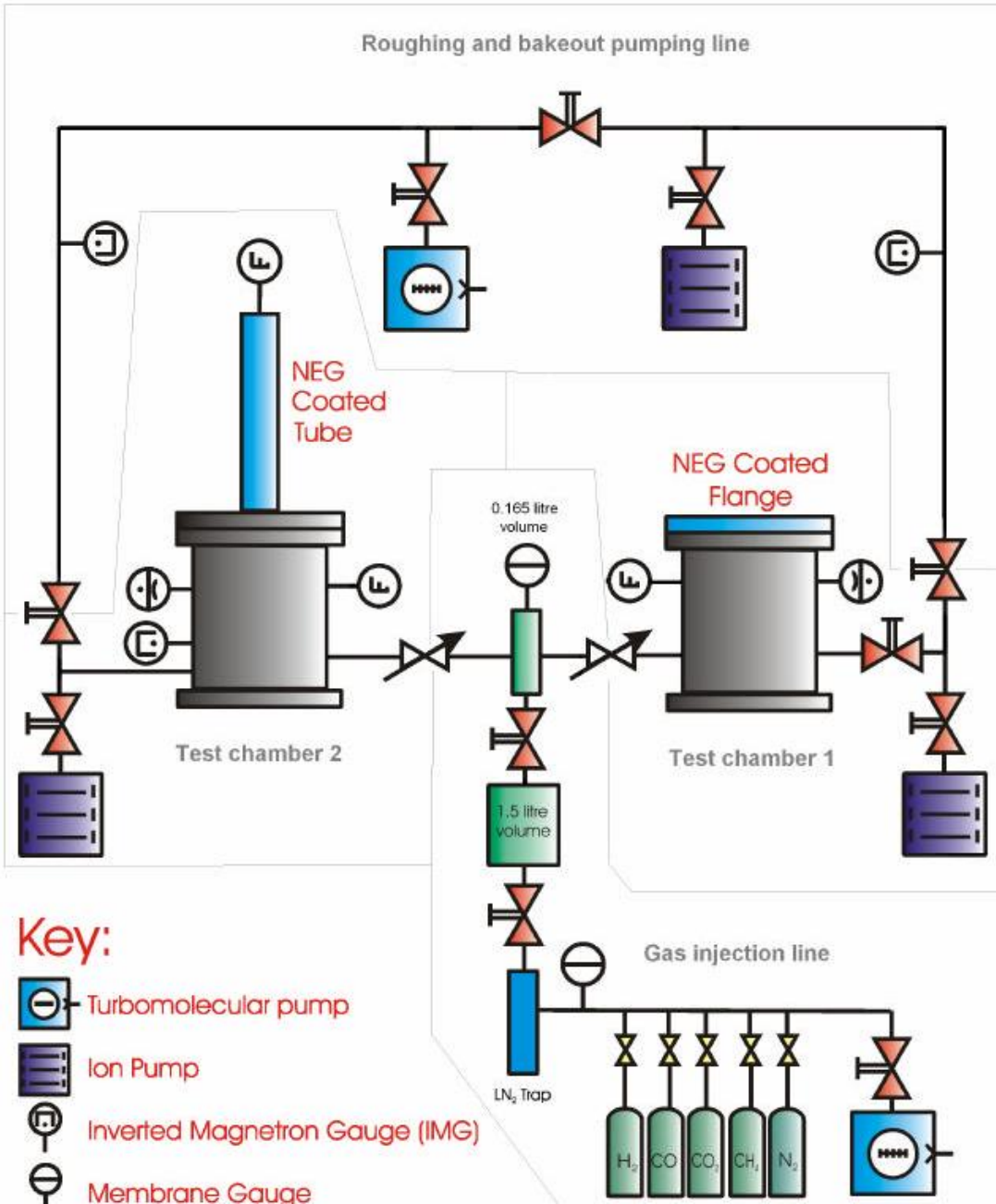


dense



O.B. Malyshev, R. Valizadeh, J.S. Colligon *et al.* J. Vac. Sci. Technol. A 27 (2009), p. 521.



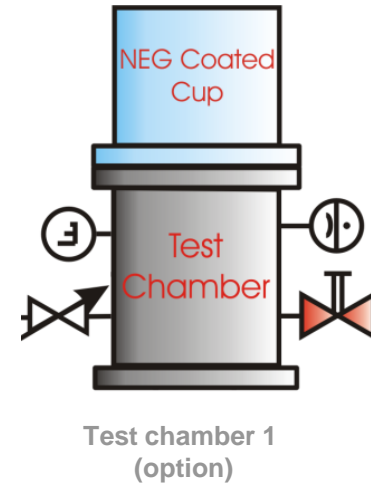


### Key:

- Turbomolecular pump
- Ion Pump
- Inverted Magnetron Gauge (IMG)
- Membrane Gauge

*O.B. Malyshev and K.J. Middleman.  
Vacuum 83 (2009), p. 976.*

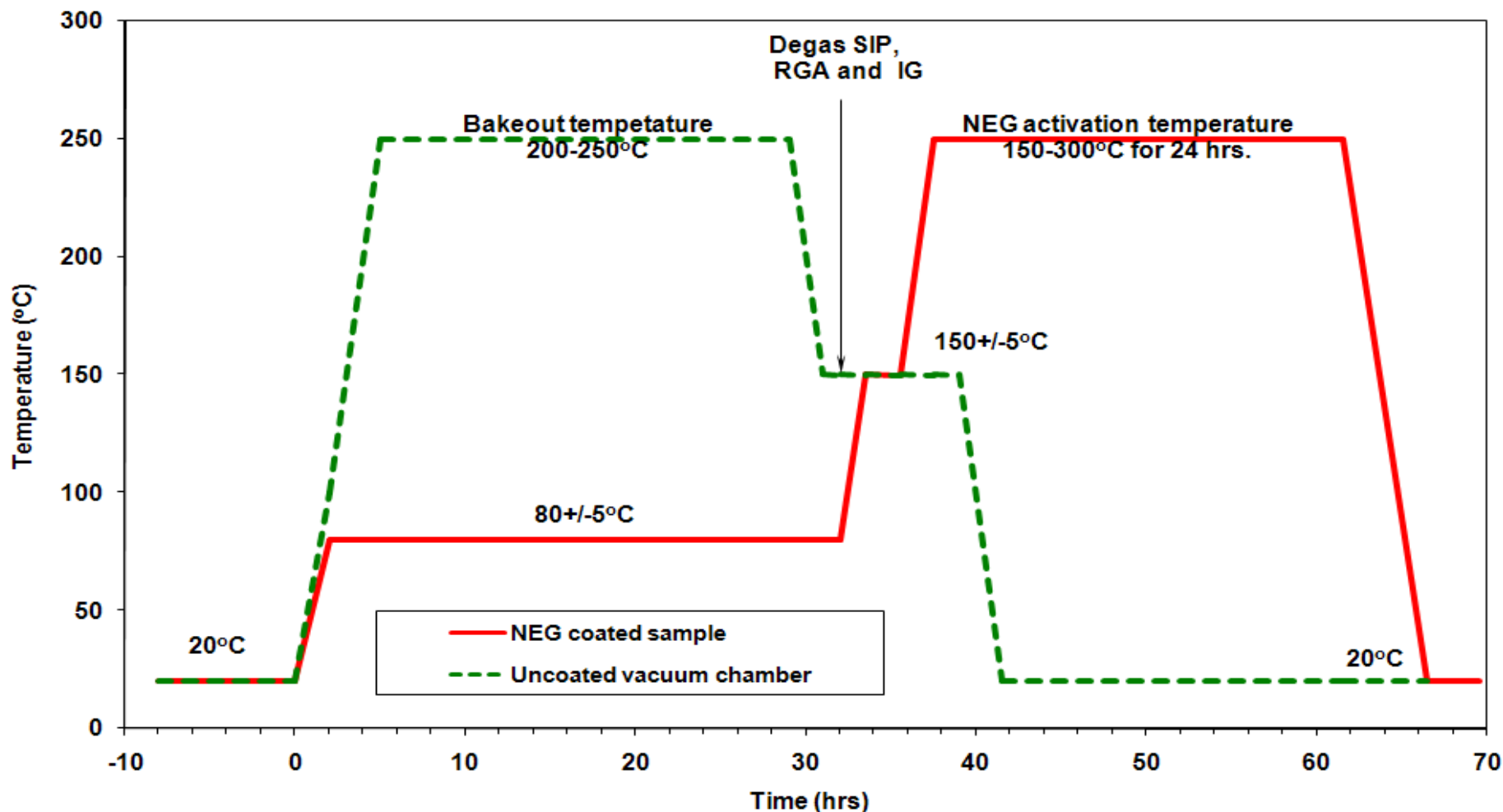
*O.B. Malyshev et al.  
J. Vac. Sci. Technol. A 27 (2009), p. 321.*



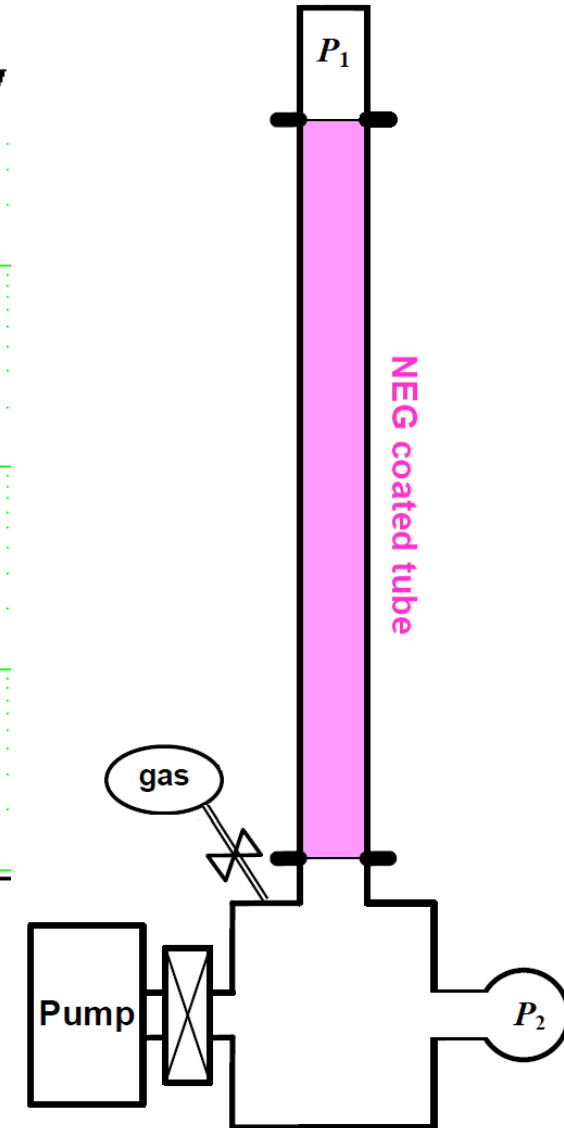
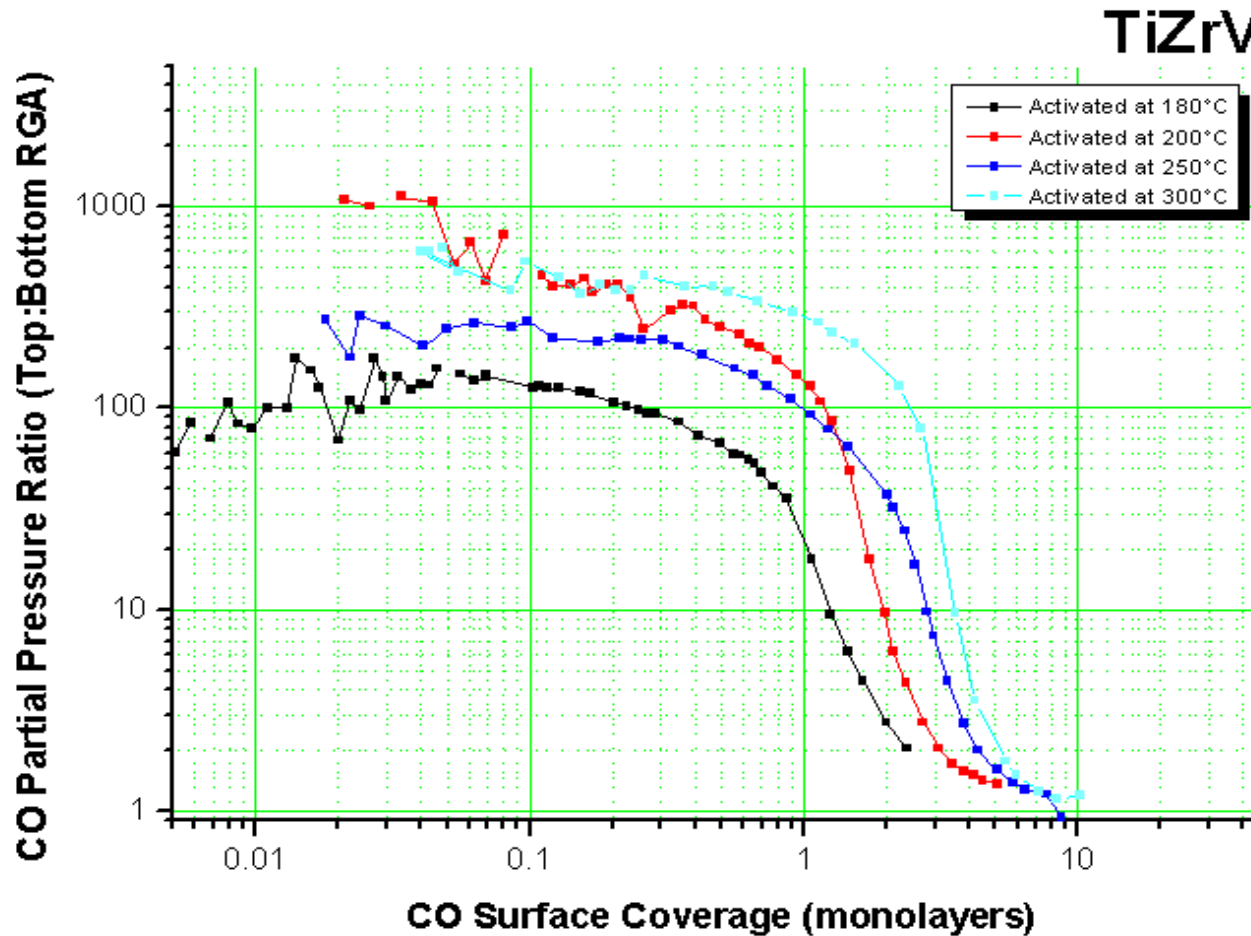
- Residual Gas Analyser (RGA)
- Extractor Gauge
- Fine Leak Valve



# ASTeC activation procedure

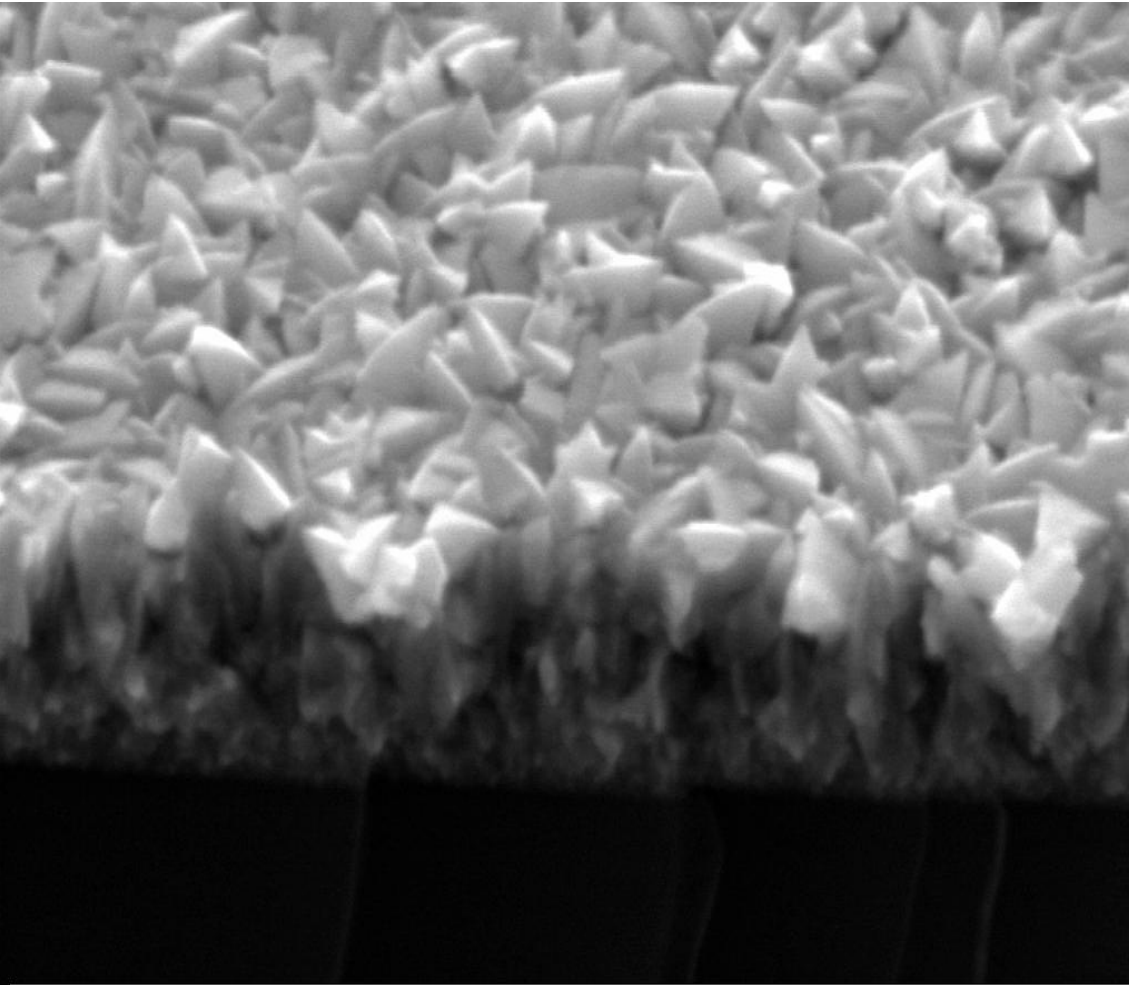


O.B. Malyshev, K.J. Middleman, J.S. Colligon and R. Valizadeh. *J. Vac. Sci. Technol. A* 27 (2009), p. 321.



Pressure ratio  $P_1/P_2$  measured during gas injection is used to estimate:  
 initial sticking probability and sorption capacity

## Titanium film deposited on Si test sample from a single Ti wire



Cylindrical Magnetron:

Power = 60 W,

$P_{Kr} = 10^{-2}$  mbar,

deposition rate = 0.14 nm/s,

$T = 120^{\circ}\text{C}$ .

Average grain size 100 – 150 nm.

200 nm



EHT = 10.00 kV

WD = 6 mm

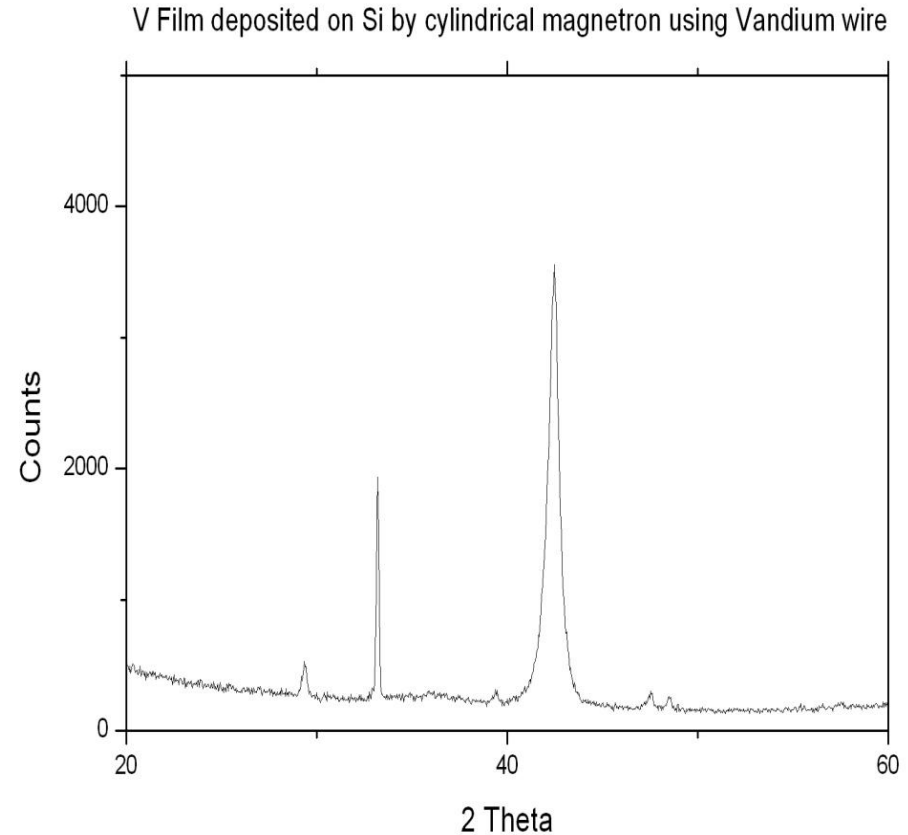
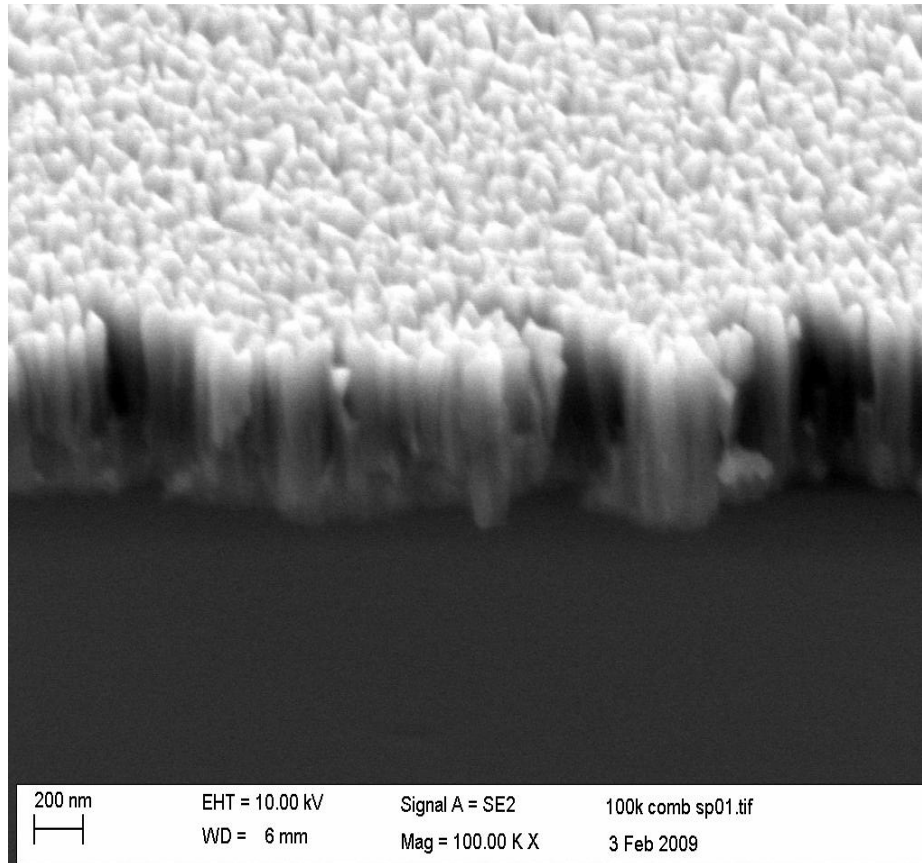
Signal A = SE2

Mag = 100.00 K X

Ti 100k.tif

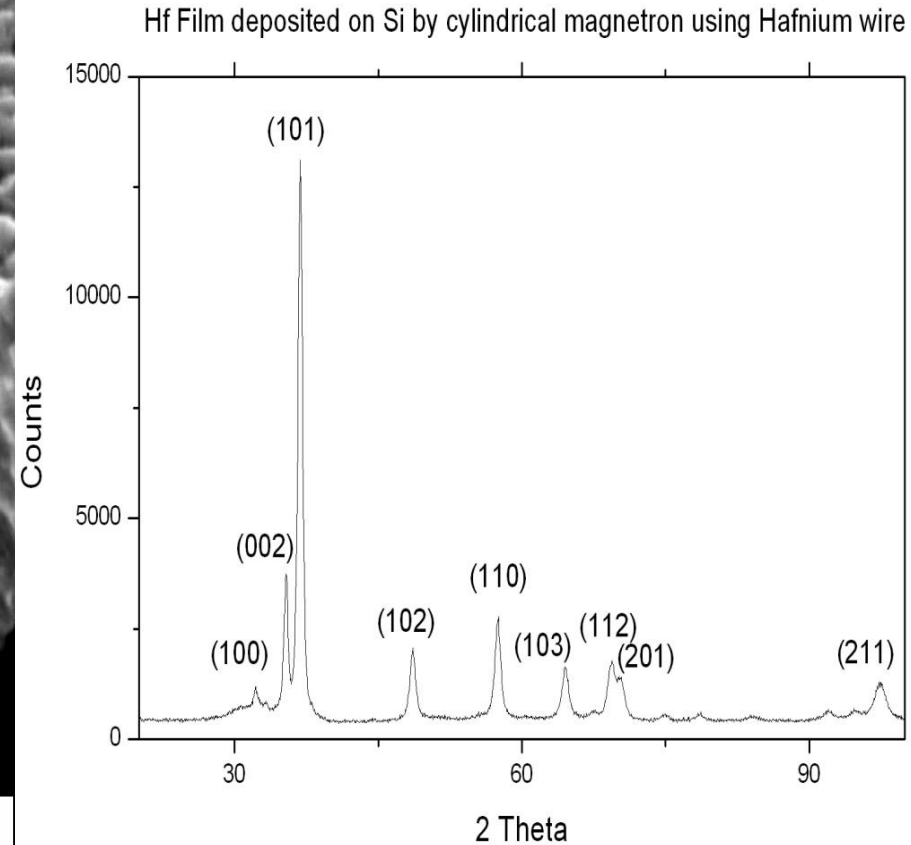
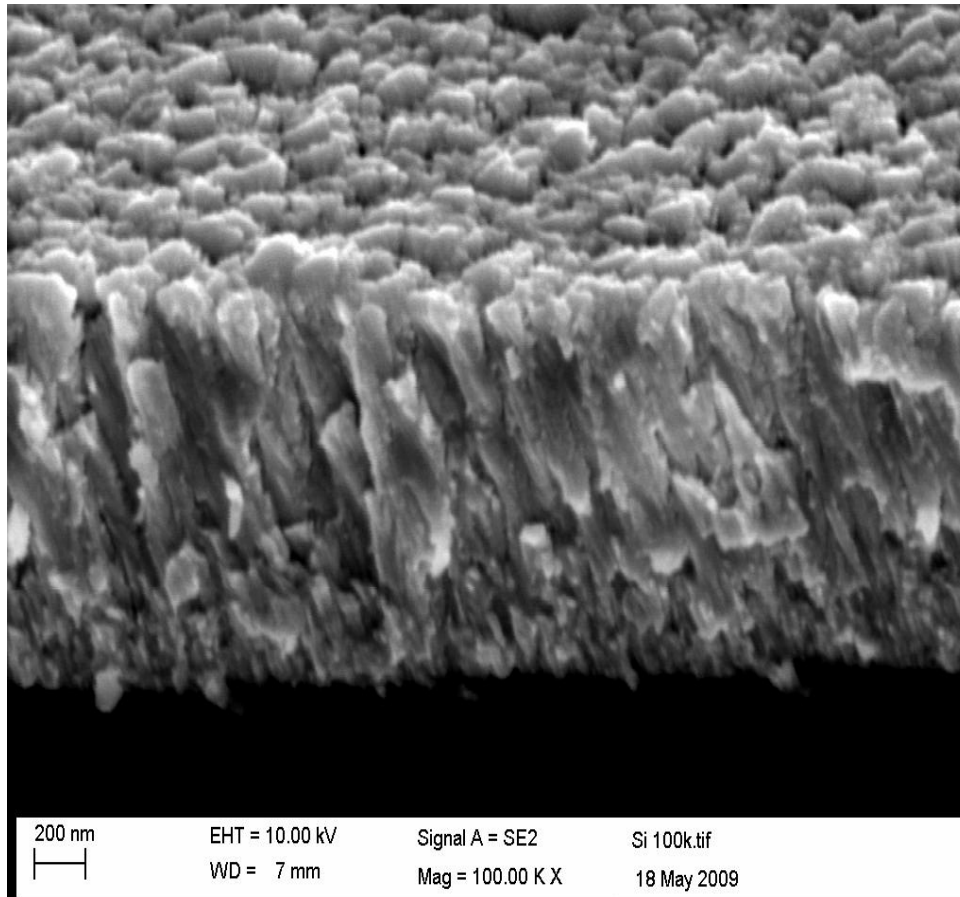
18 May 2009

## Vanadium film deposited on Si test sample from a single V wire.



Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.16 nm/s,  $T = 120^{\circ}\text{C}$ .  
Average grain size 100 nm. Rhombohedral lattice structure.

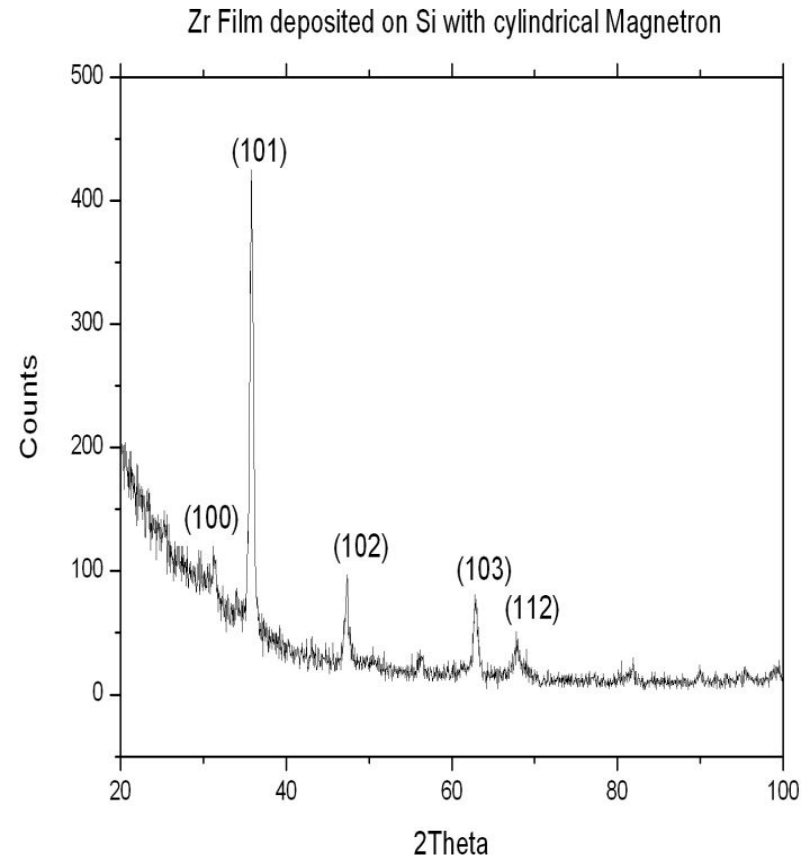
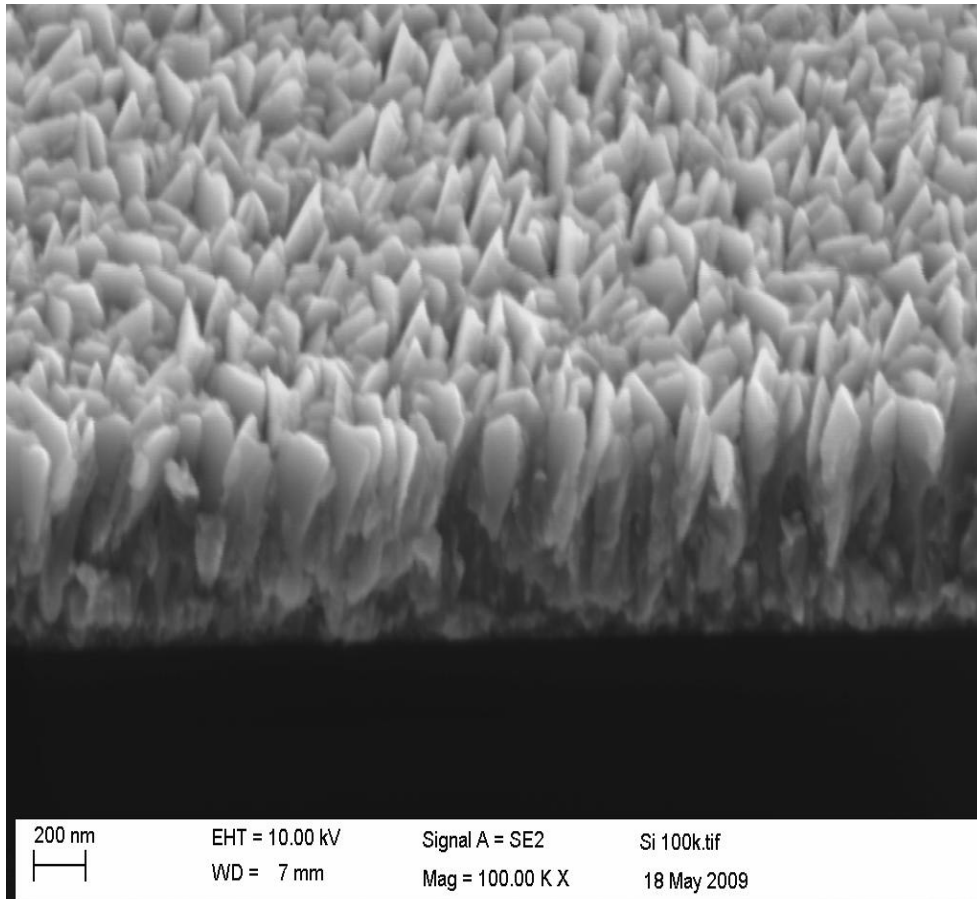
## Hf film deposited on Si test sample from a single Hf wire.



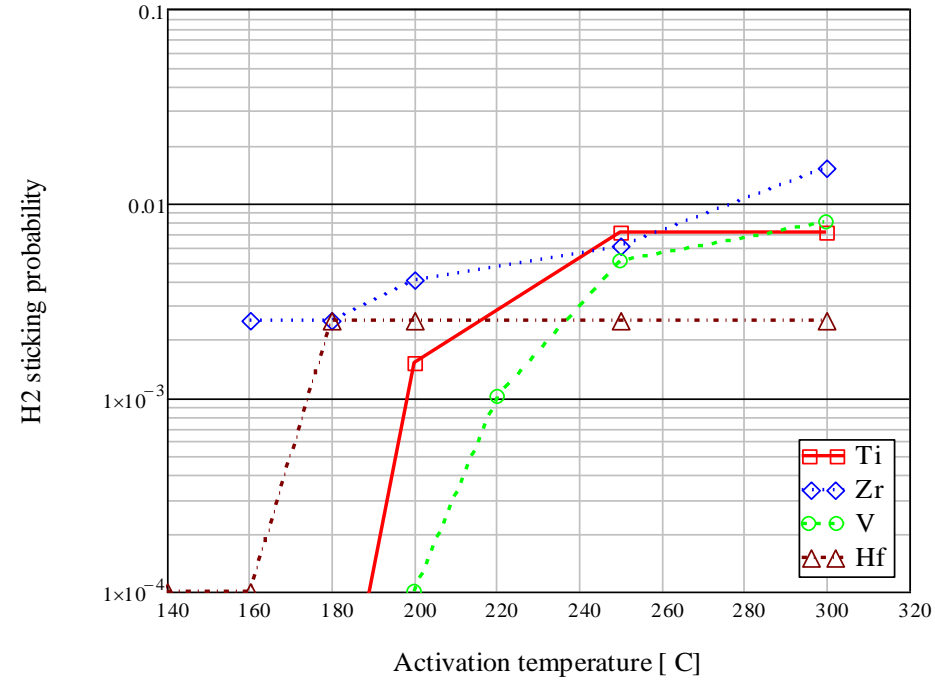
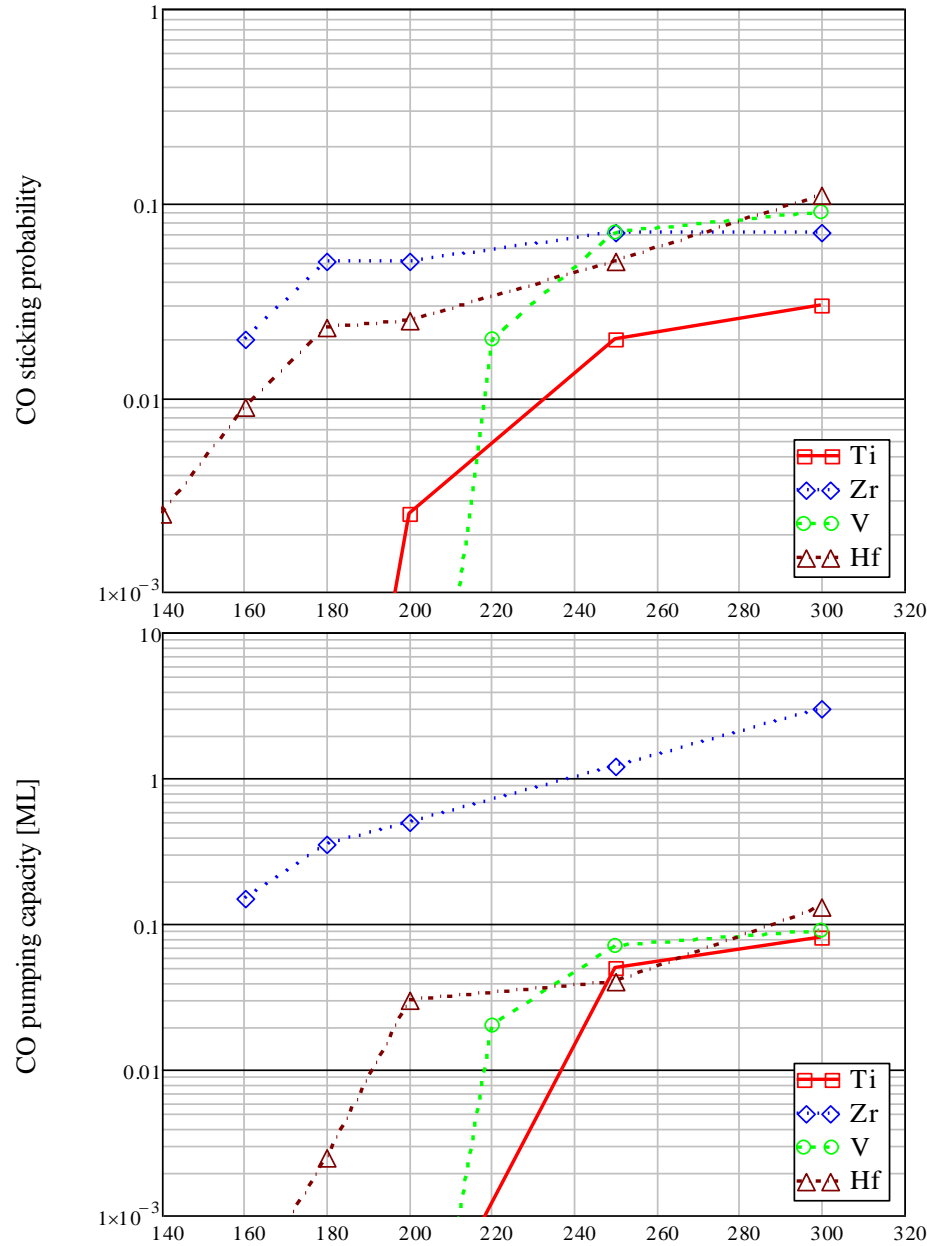
Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.16 nm/s,  $T = 120^{\circ}\text{C}$ .  
 Average grain size 100 – 150 nm. Hexagonal lattice structure.



## Zr film deposited on a Si test sample from a single Zr wire



Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.14 nm/s,  $T = 120^{\circ}\text{C}$ .  
 Average grain size 100 – 150 nm. Hexagonal lattice structure.



**Zr** is best:

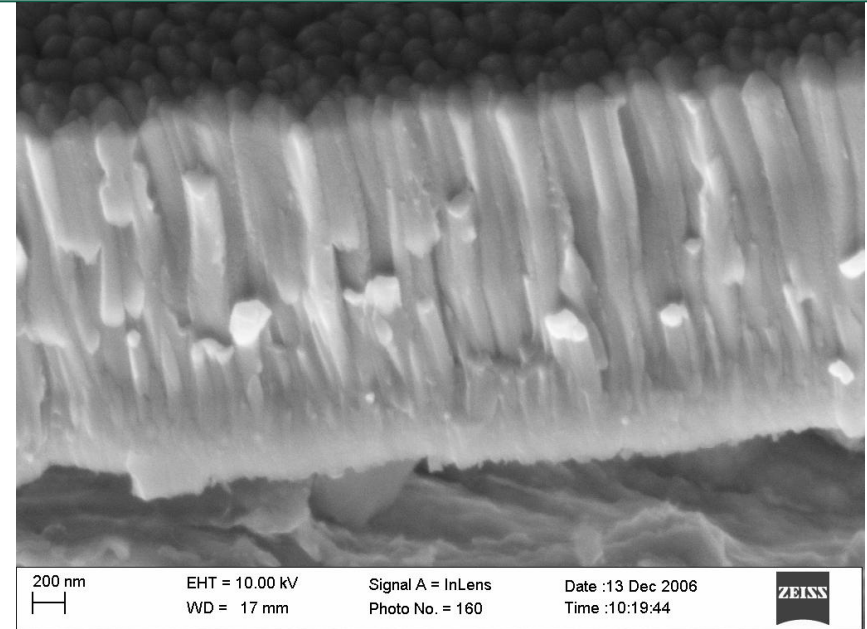
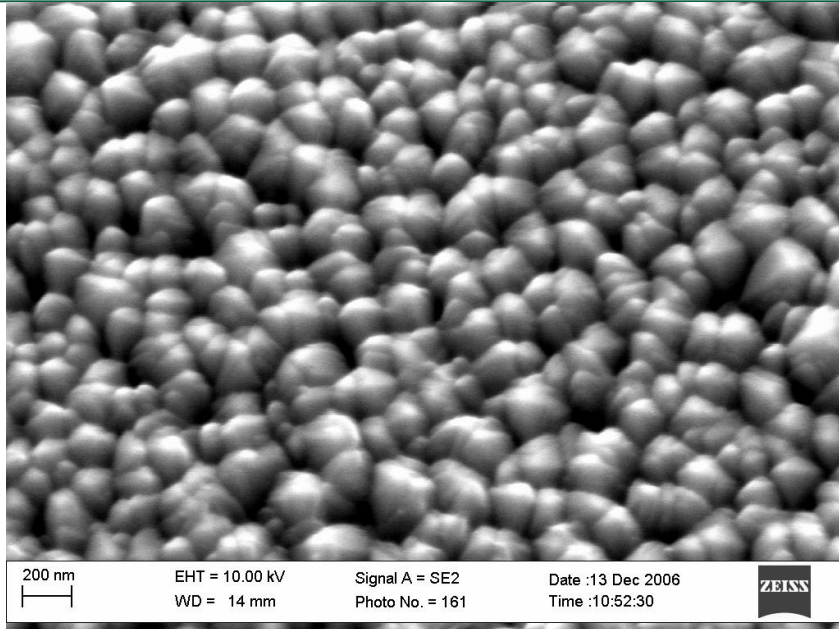
Lowest activation Temp. and highest capacity

**Hf**

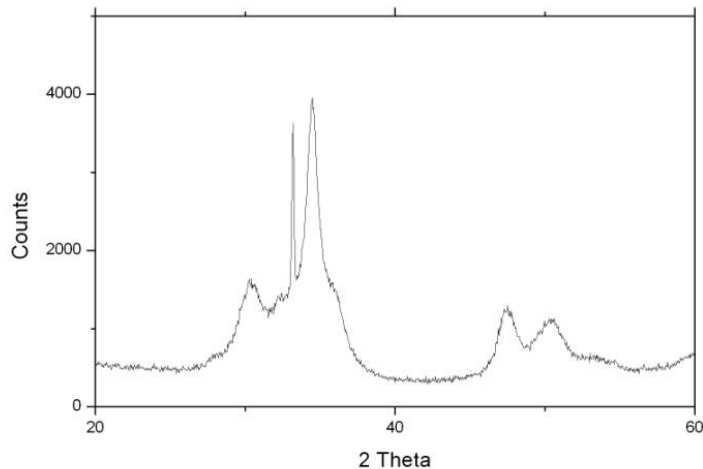
**Ti**

**V** has highest activation temperature

## Ti-V film deposited on Si test sample from twisted Ti and V wires.



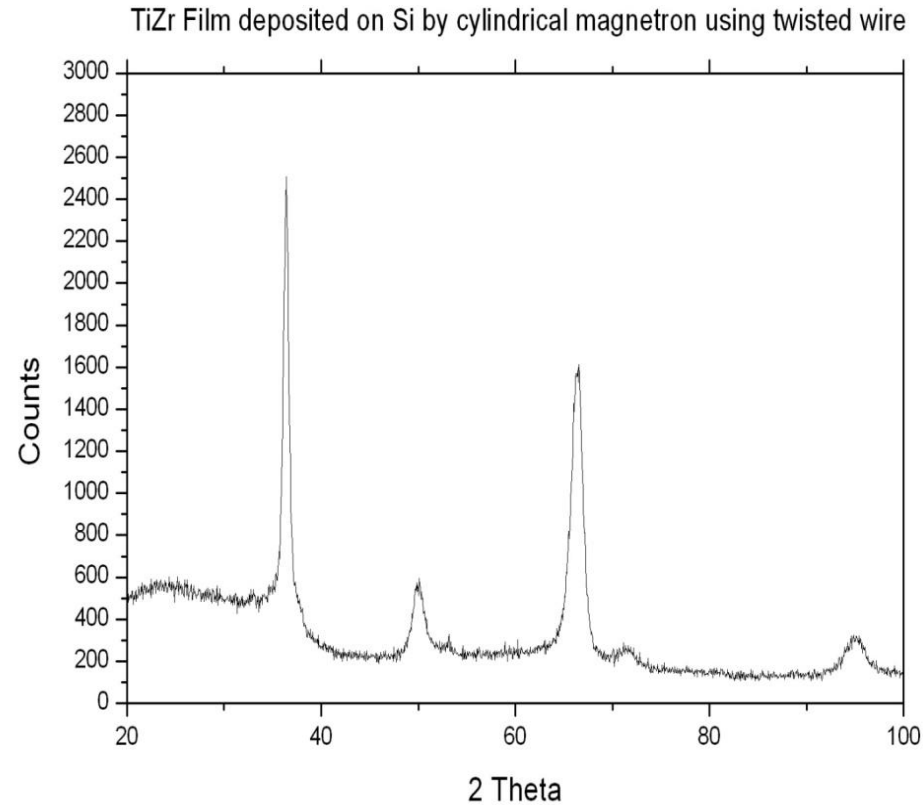
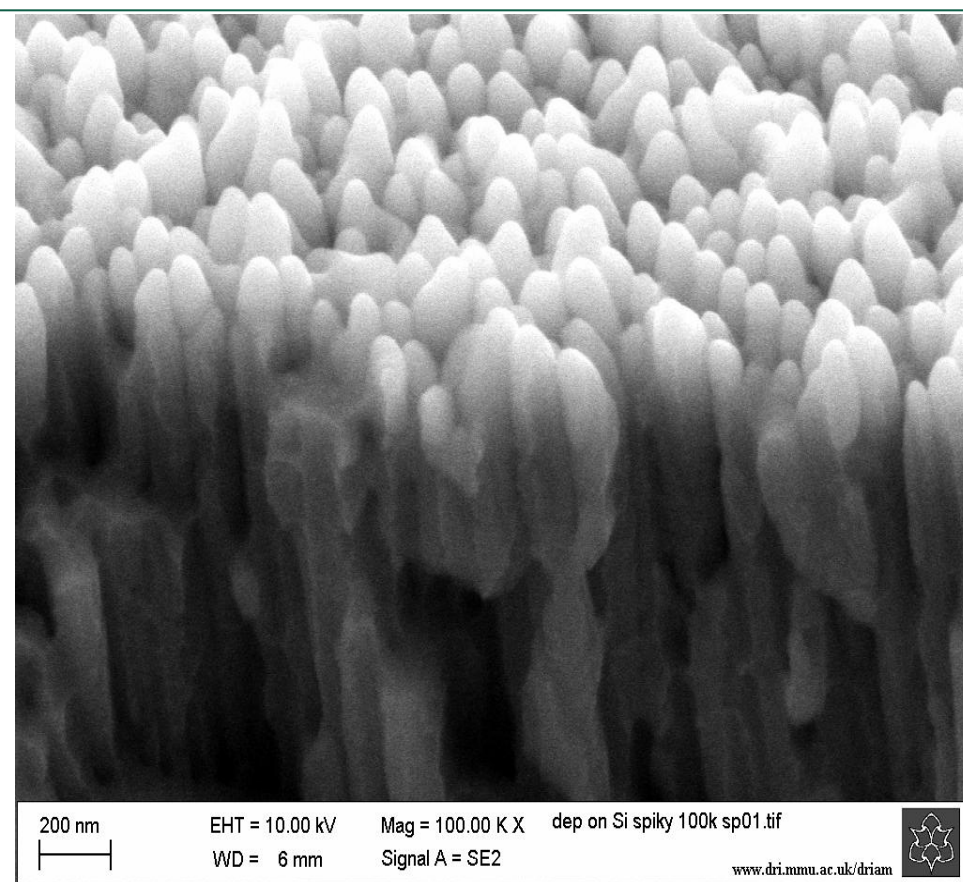
TiV Film deposited on Si by cylindrical magnetron with twisted wire



Cylindrical Magnetron:  
 Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar,  
 deposition rate = 0.13 nm/s,  $T = 120^{\circ}\text{C}$ .  
 Average grain size 50 – 100 nm.  
 Hexagonal lattice structure.

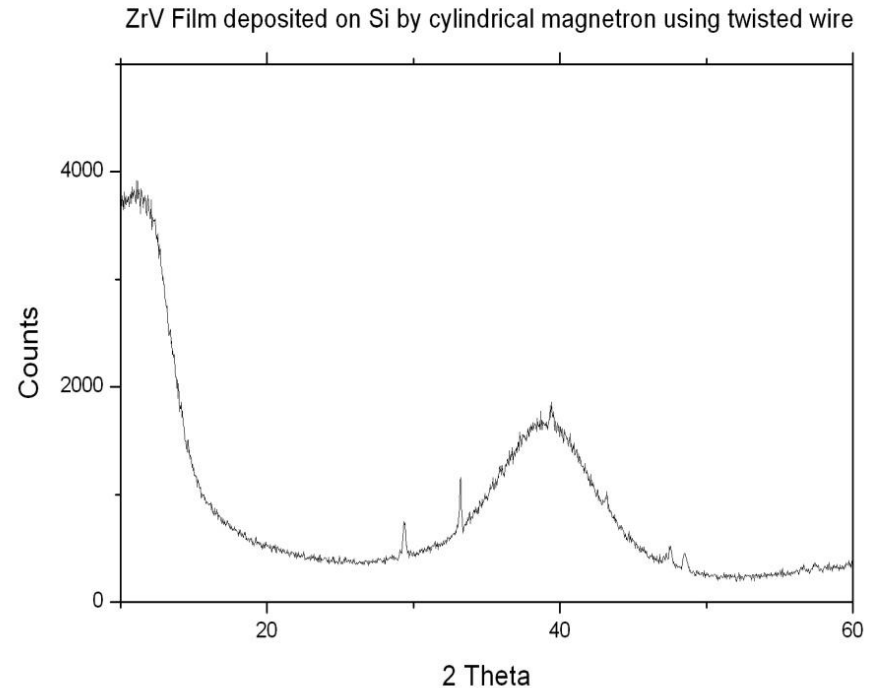
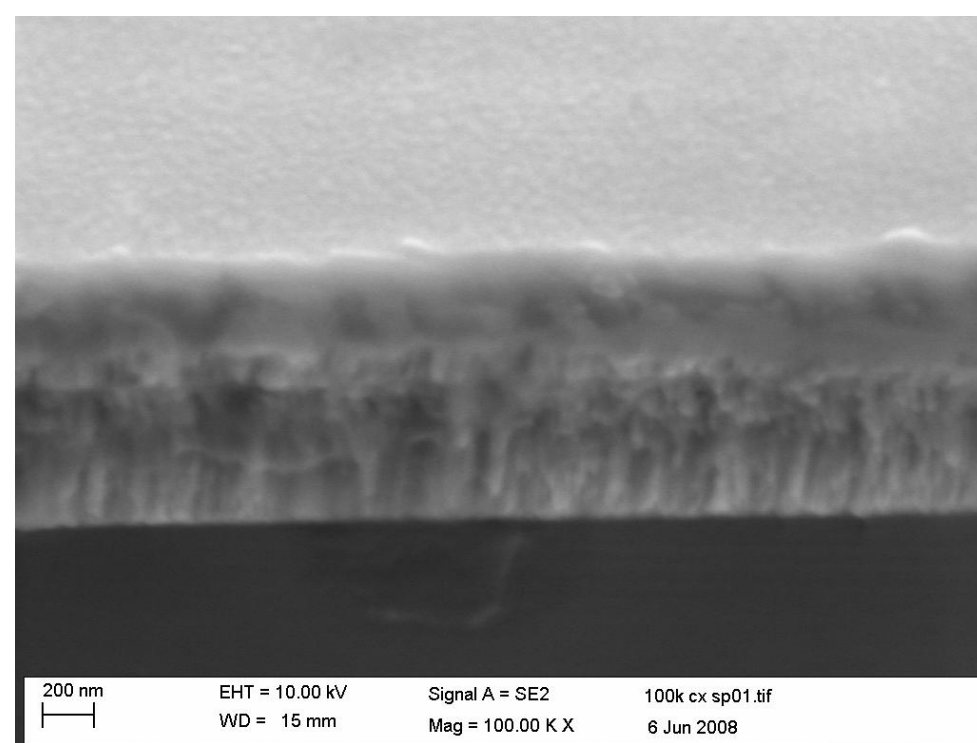


## Ti-Zr film deposited on Si test sample from twisted Ti and Zr wires

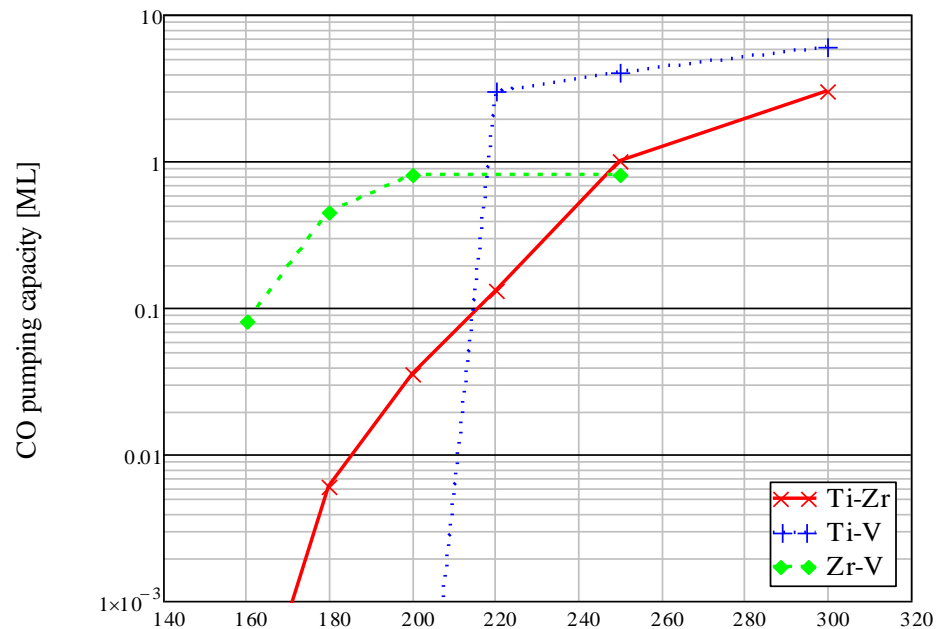
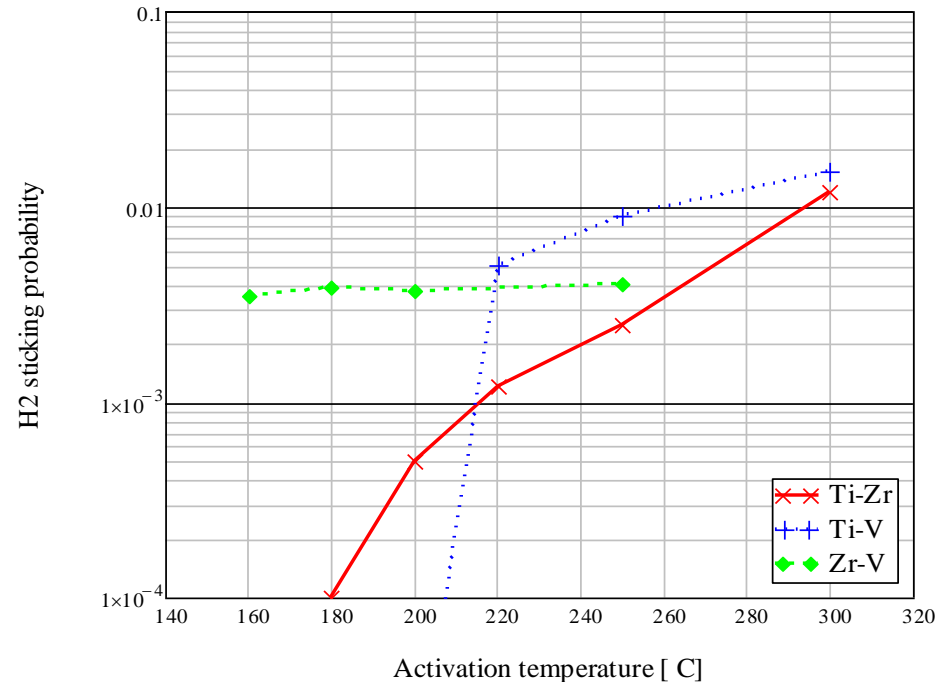
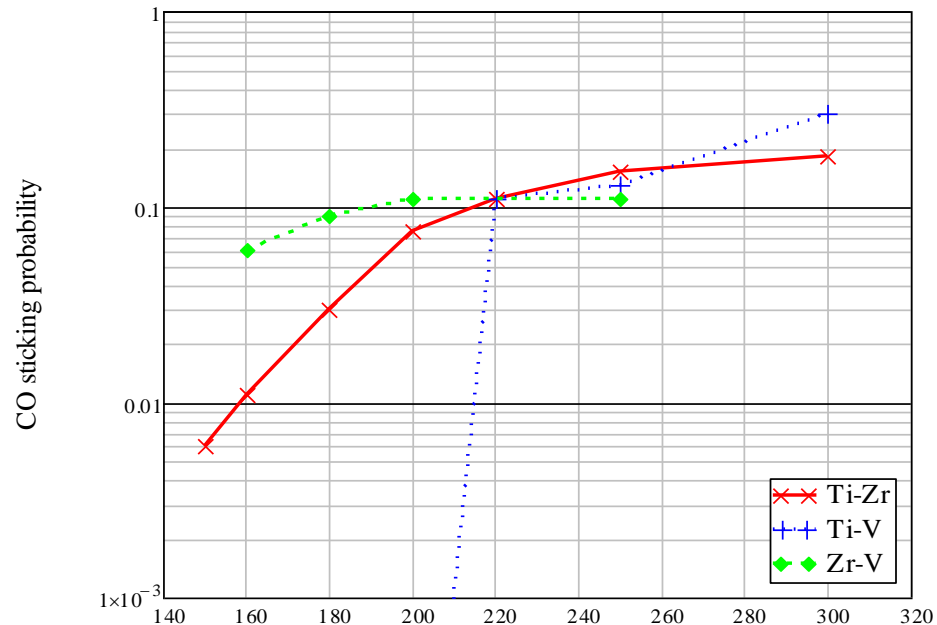


Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.16 nm/s,  $T = 120^{\circ}\text{C}$ .  
Average grain size 50 – 100 nm. Hexagonal lattice structure.

## Zr-V film deposited on Si test sample from twisted Zr and V wires.



Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.15 nm/s,  $T = 120^{\circ}\text{C}$ .  
Average grain size **10 – 20 nm**.



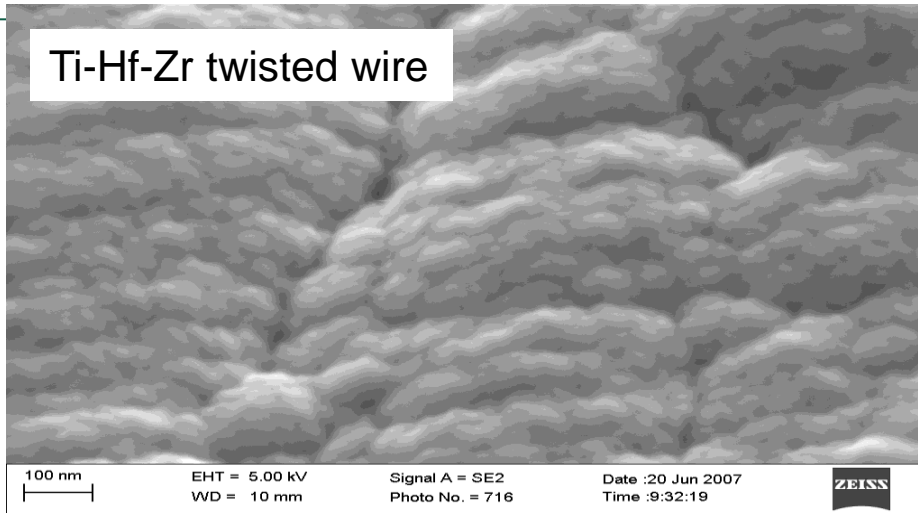
Zr-V is best

Ti-Zr activation temperature is lower than for Ti-V

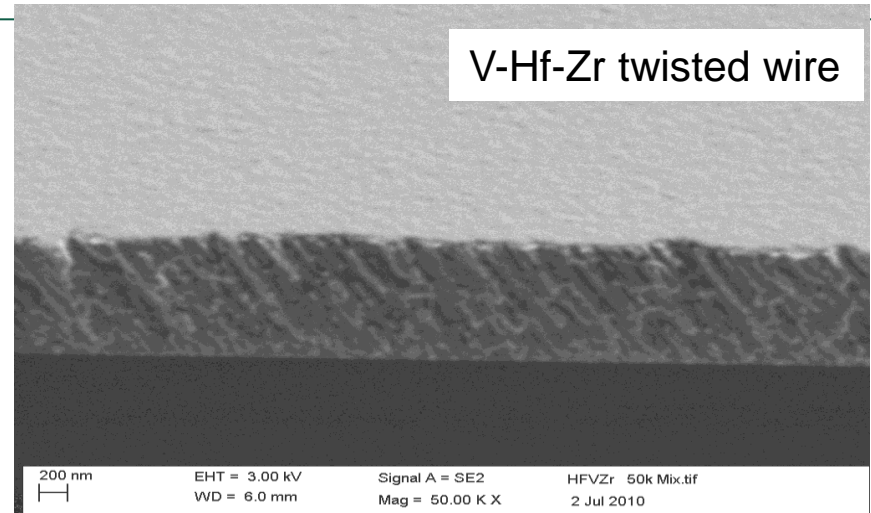
Zr-Hf was not studied

## Ternary NEG film deposited on Si test sample from twisted Ti, V, Zr, and Hf wires and TiZrV alloy wire

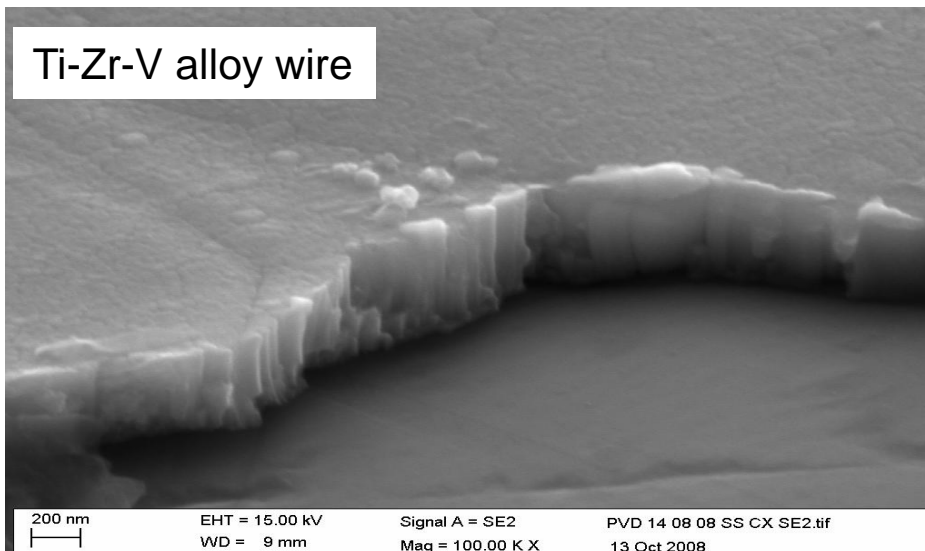
Ti-Hf-Zr twisted wire



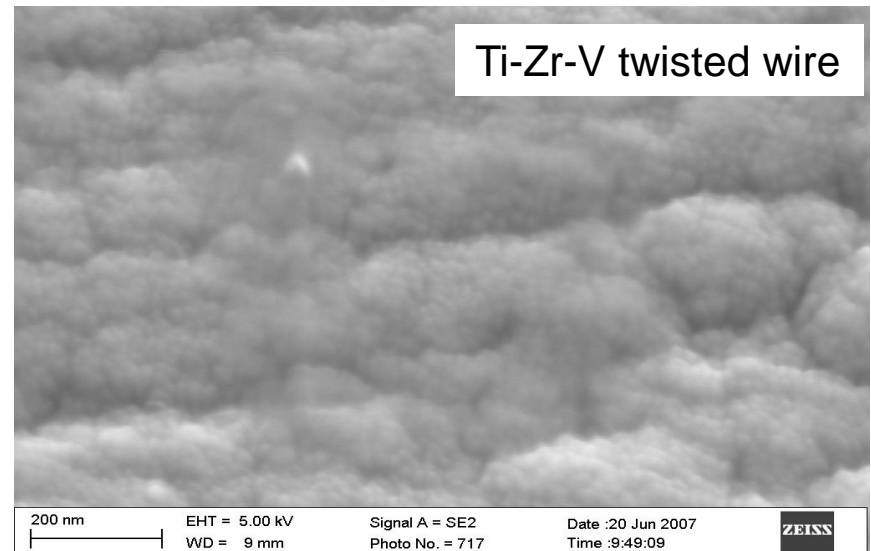
V-Hf-Zr twisted wire



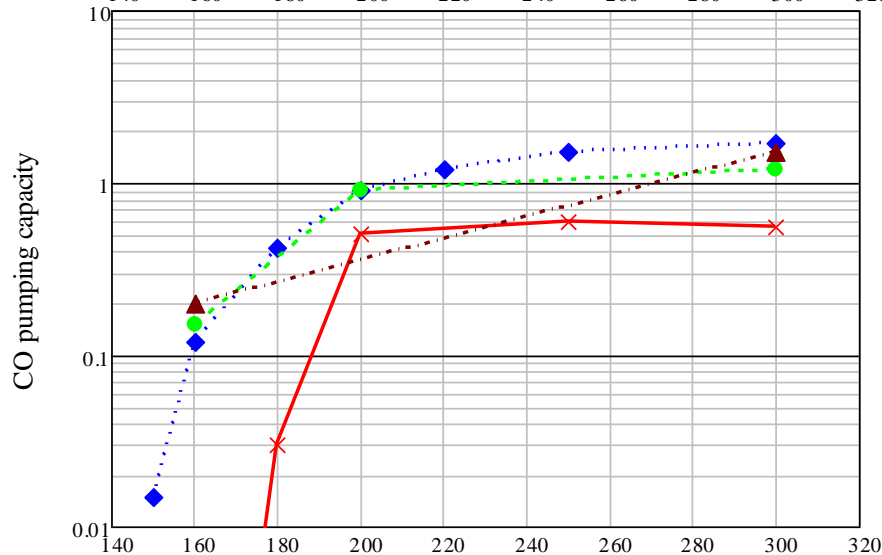
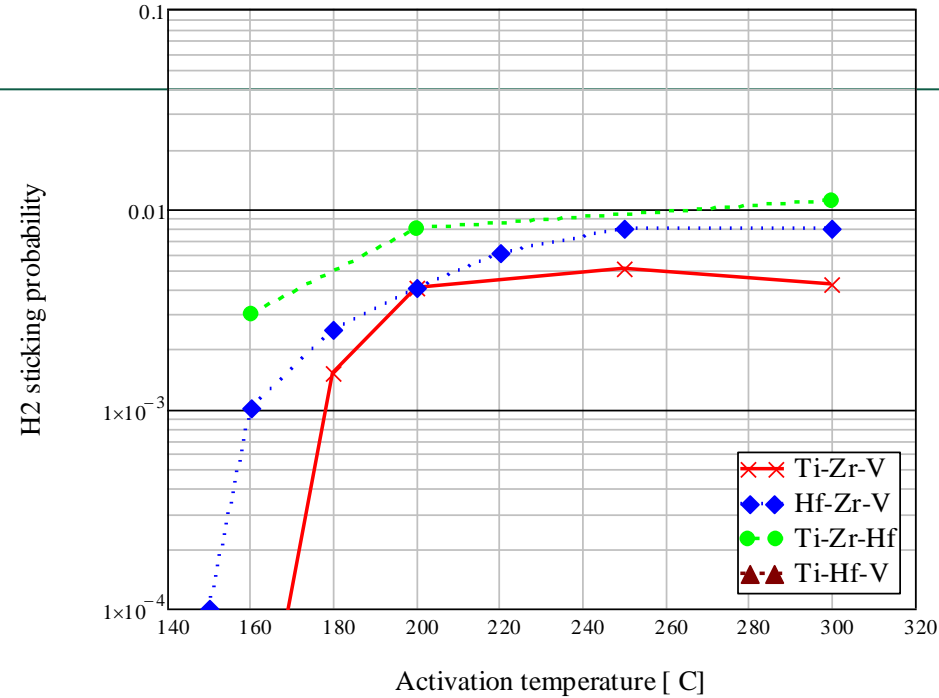
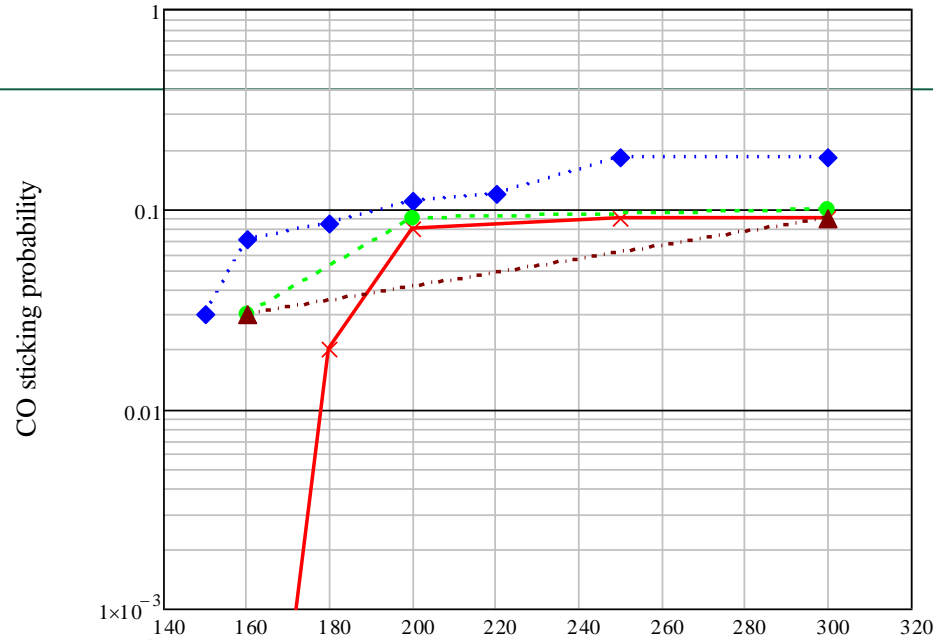
Ti-Zr-V alloy wire



Ti-Zr-V twisted wire



Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.12 nm/s,  $T = 120^\circ\text{C}$ .  
 Average grain size 5 nm. Hexagonal lattice structure.

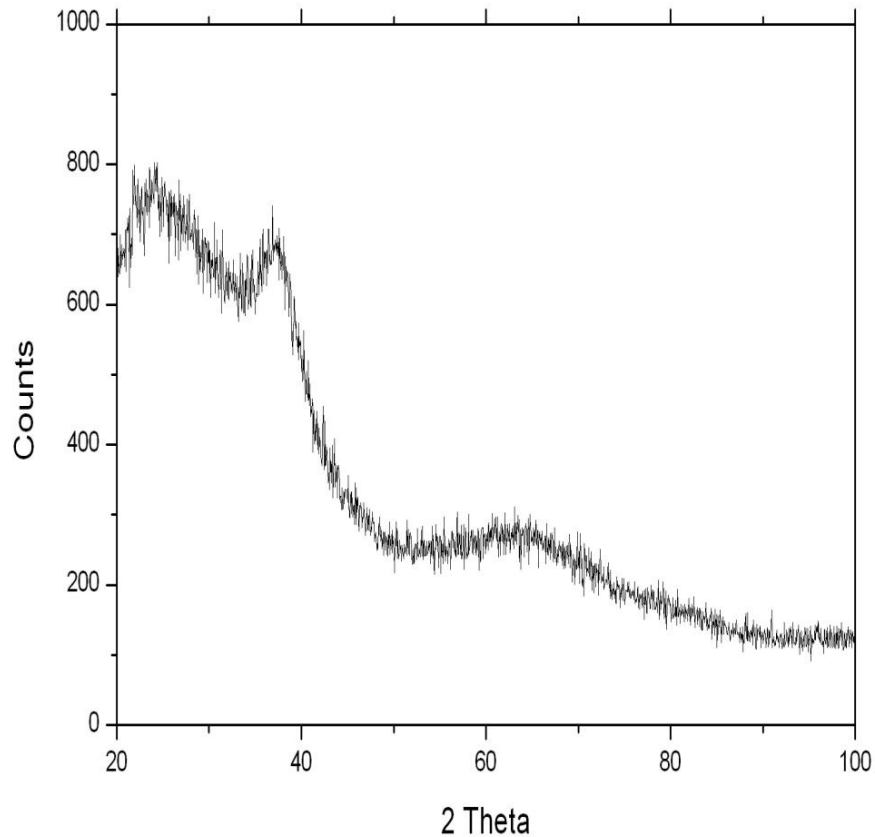


Hf-Zr-V, Ti-Zr-Hf and Ti-Hf-V are comparable

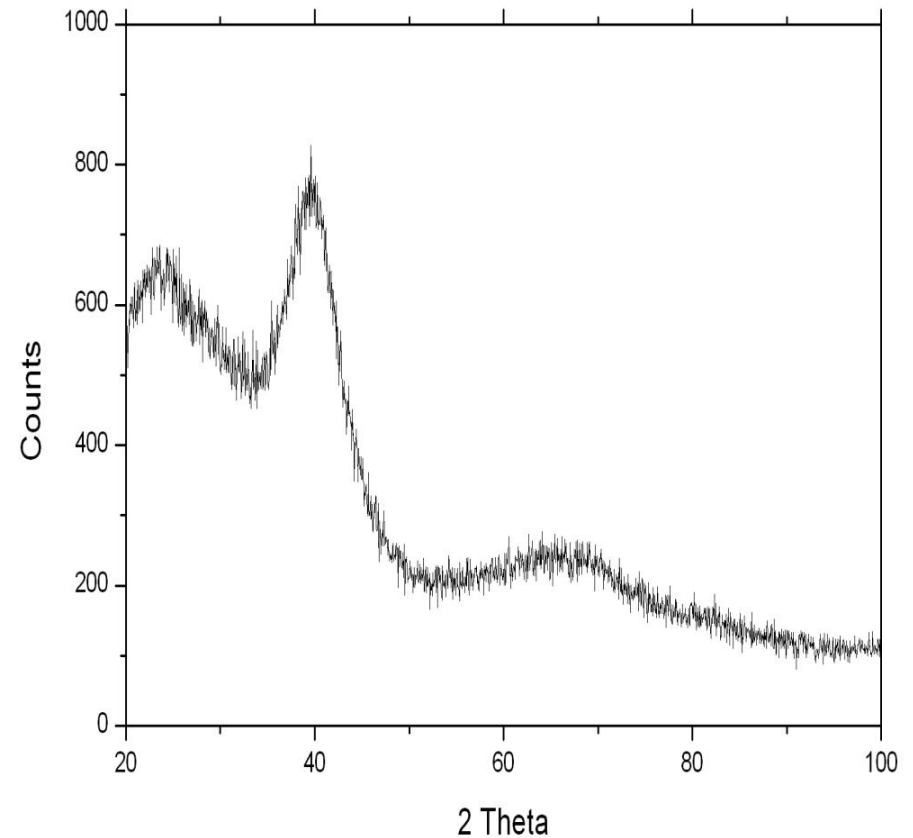
Ti-Zr-V has the highest activation temperature

## XRD of Ti-Zr-V film: alloy wire vs. twisted wires as target.

TiZrV Film deposited on Si by cylindrical magnetron using Alloy wire



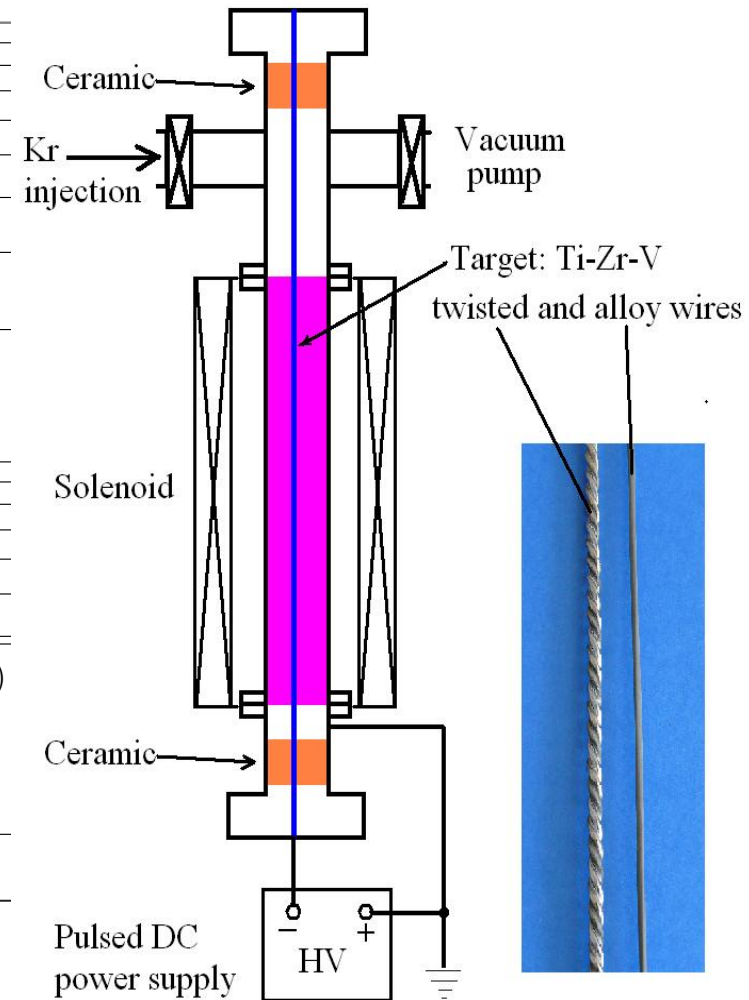
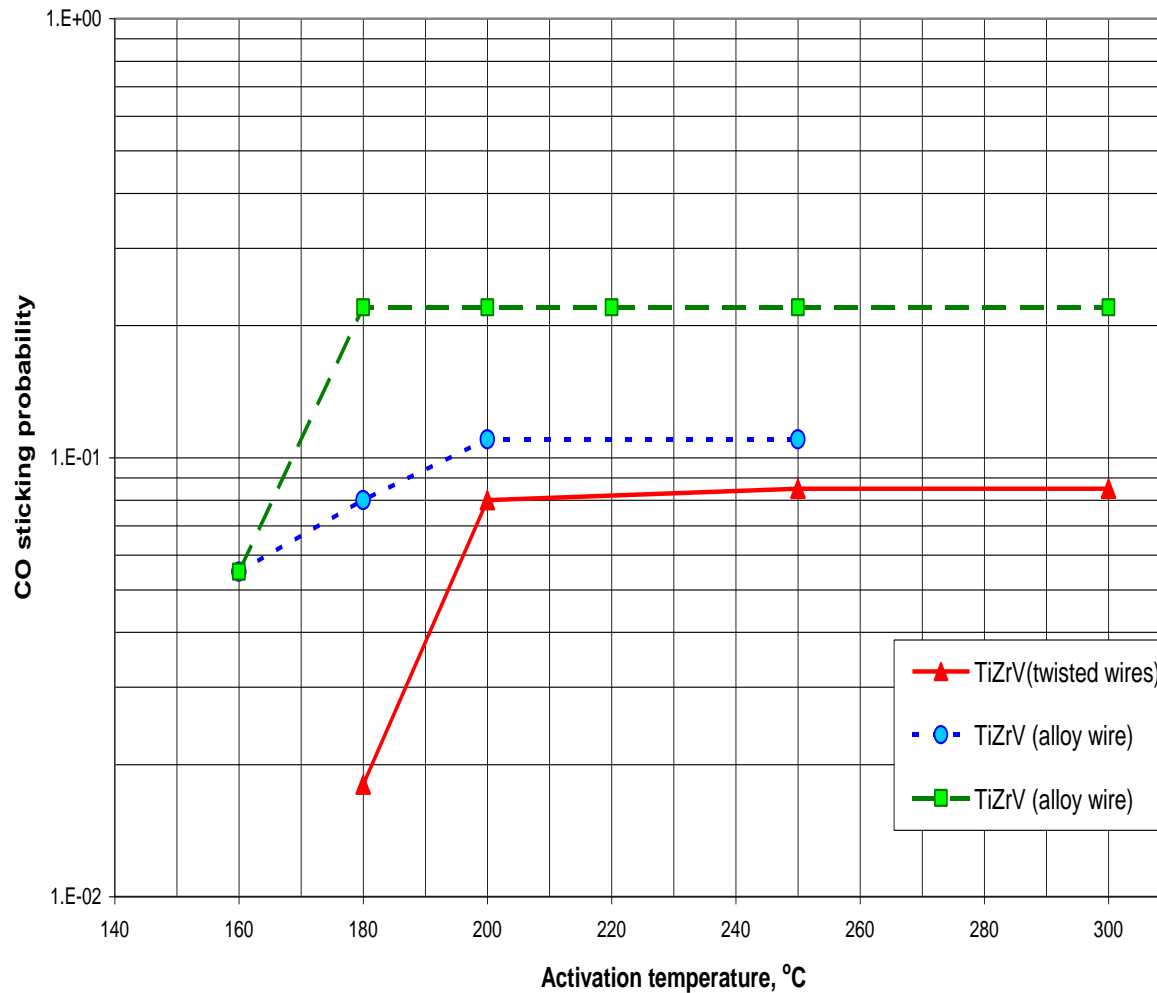
TiZrV Film deposited on Si by cylindrical magnetron using twisted wire



In Both cases there is only one broad peak near  $2\theta = 40^\circ$   
The film is nearly amorphous.

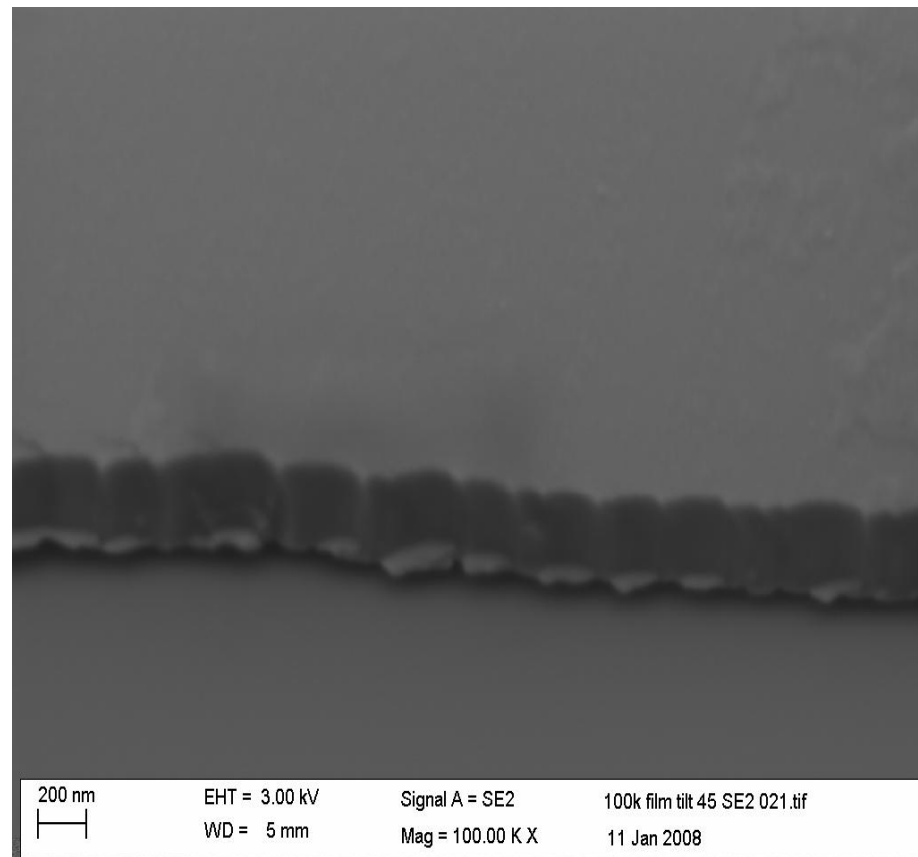
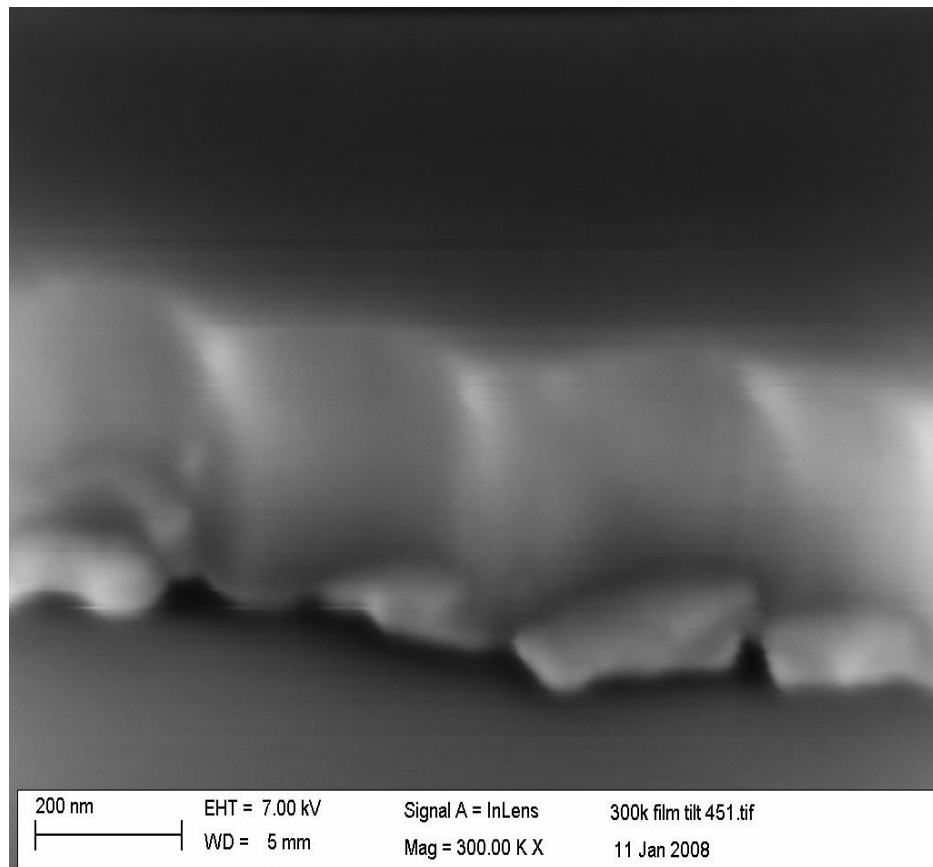


# Twisted wires vs. alloy target: reducing $T_a$



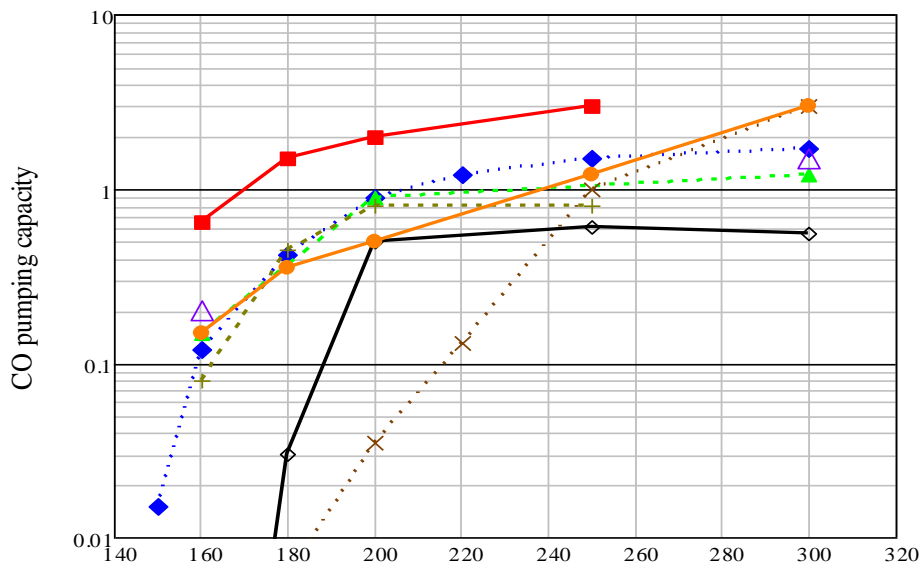
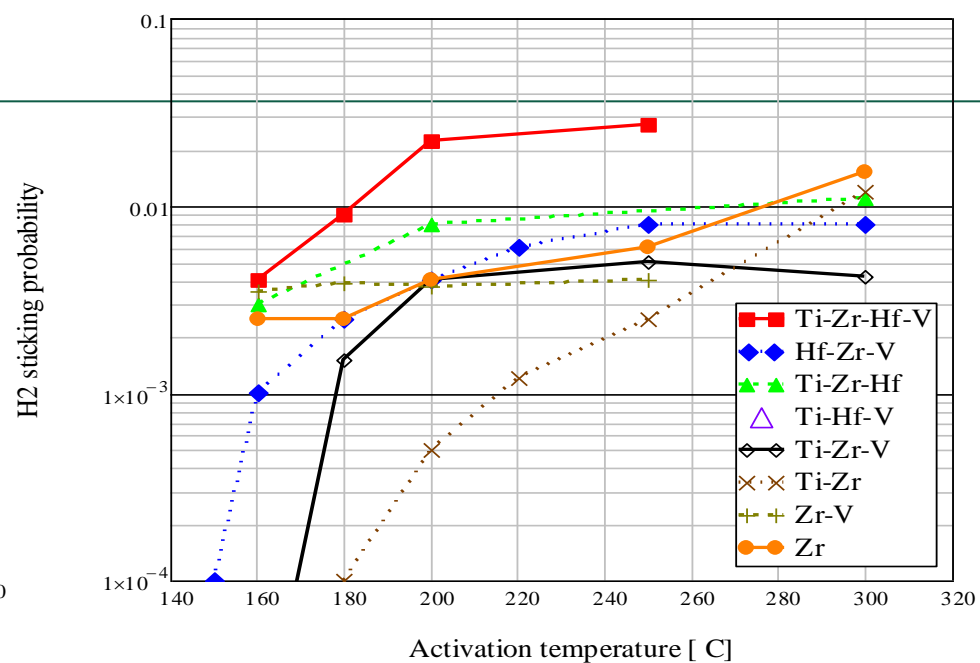
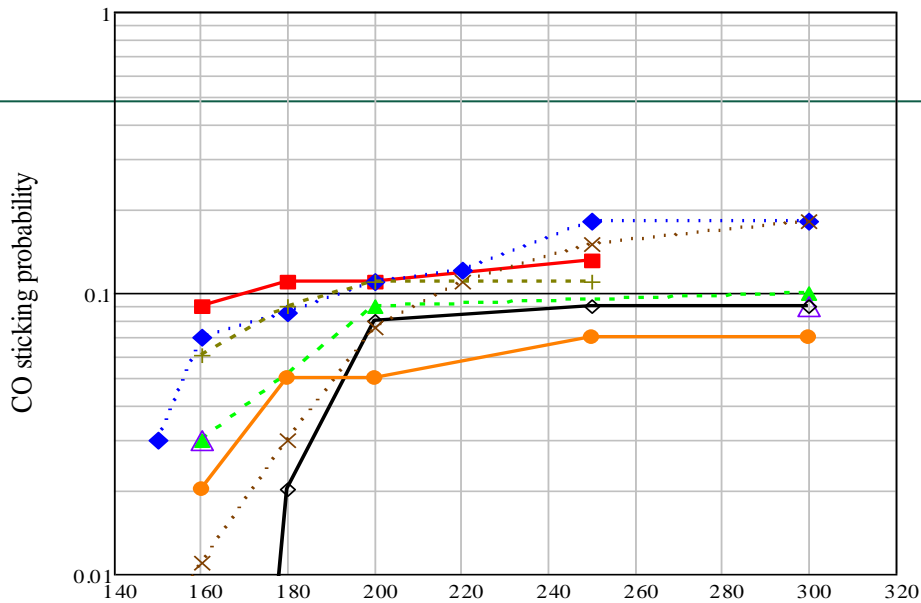
R. Valizadeh, O.B. Malyshev, J.S. Colligon, V. Vishnyakov. Accepted by J. Vac. Sci. Technol. Aug. 2010.

## Quaternary NEG alloy film deposited on Si test sample from twisted Ti, V, Zr, and Hf wires.



Cylindrical Magnetron: Power = 60 W,  $P_{Kr} = 10^{-2}$  mbar, deposition rate = 0.12 nm/s,  $T = 120^{\circ}\text{C}$ .  
Very glassy structure.





**Ti-Zr-Hf-V** is the best  
**Hf-Zr-V, Ti-Zr-Hf, Ti-Hf-V** and  
**Zr** are comparable  
**Ti-Zr-V** is lower  
**Zr-V** (best binary alloy) has the  
 lowest activation temperature

## Pressure in the accelerator vacuum chamber

$$P \propto \frac{\eta}{\alpha}$$

where

- $\eta$  - desorption yield
- $\alpha$  - sticking probability

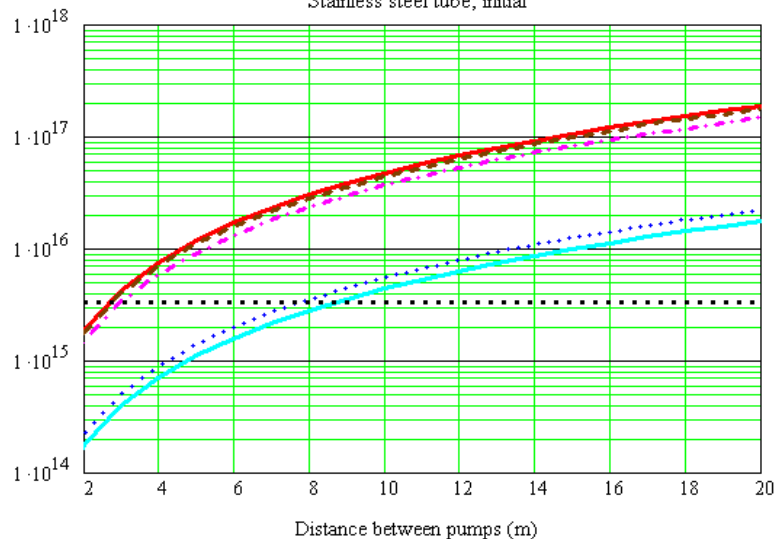
- Improving pumping properties is limited:

$$\alpha \leq 1.$$

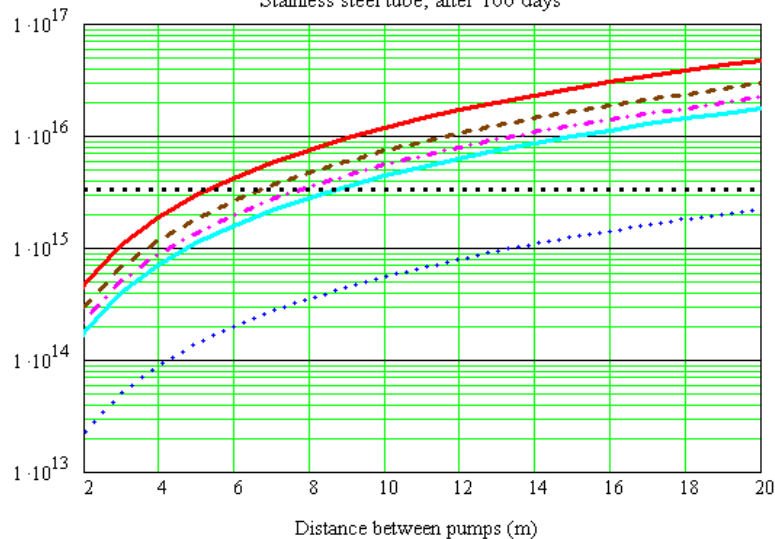
- $0.005 < \alpha_{H_2} < 0.01$
- $0.1 < \alpha_{CO} < 0.5$
- $0.4 < \alpha_{CO_2} < 0.6$
- Reducing the desorption yields  $\eta$   
• in orders of magnitude  
is a realistic task

# Average gas density in the ILC undulator: d=4 mm

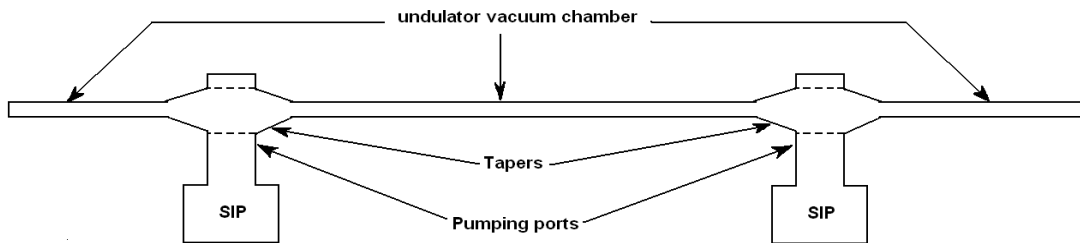
Stainless steel tube, initial



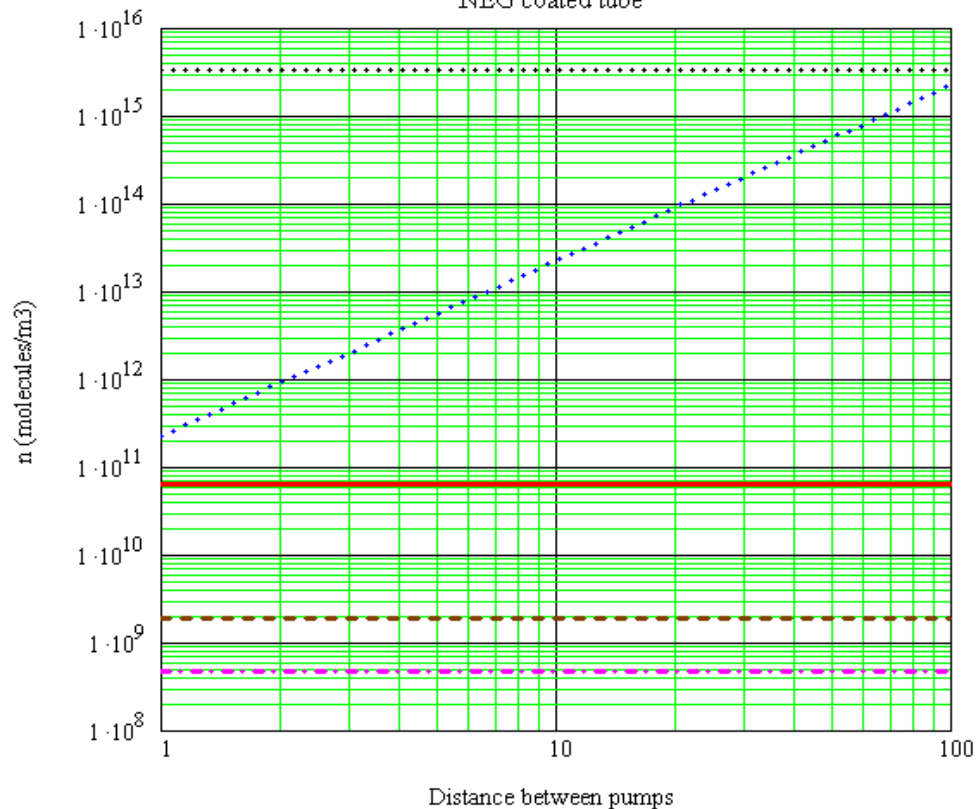
Stainless steel tube, after 100 days



- H2
- CH4
- - - CO
- · - · CO2
- Thermal desorption
- Required vacuum



NEG coated tube



- H2
- CH4
- - - CO
- · - · CO2

## Reducing the gas desorption from the NEG coatings

- Main gases in the NEG coated vacuum chamber are  $H_2$  and  $CH_4$ 
  - Only  $H_2$  can diffuse through the NEG film under bombardment or heat
  - $CH_4$  is most likely created on the NEG surface from diffused  $H_2$  and C (originally from sorbed CO and  $CO_2$ )
  - Therefore the  $H_2$  diffusion must be suppressed
    - Where  $H_2$  come from?

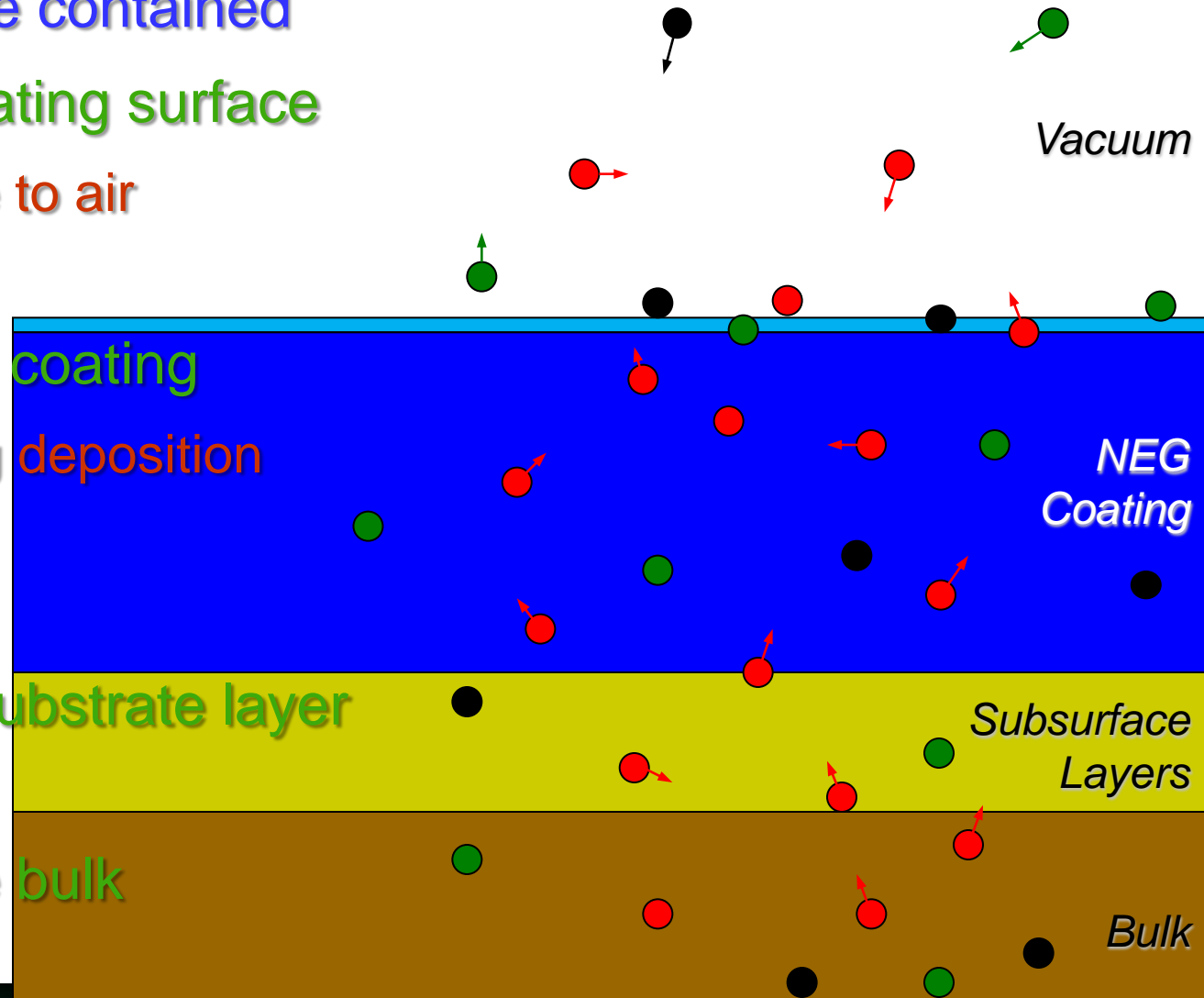
## Reducing the gas desorption from the NEG coatings

- Gas molecules are contained
  - on the NEG coating surface
  - after exposure to air

- inside the NEG coating
  - trapped during deposition

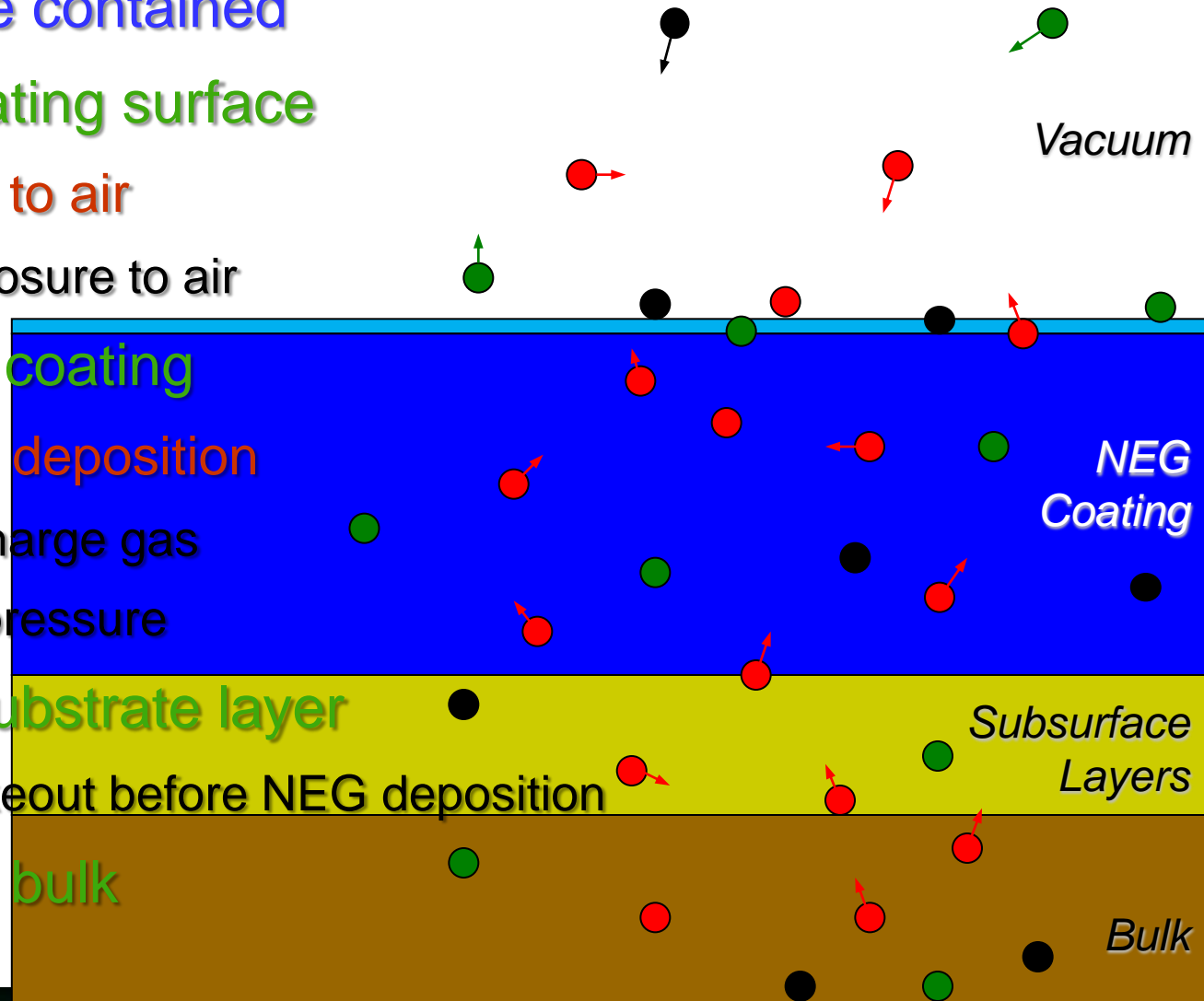
- in subsurface substrate layer

- in the substrate bulk



# Reducing the gas desorption from the NEG coatings

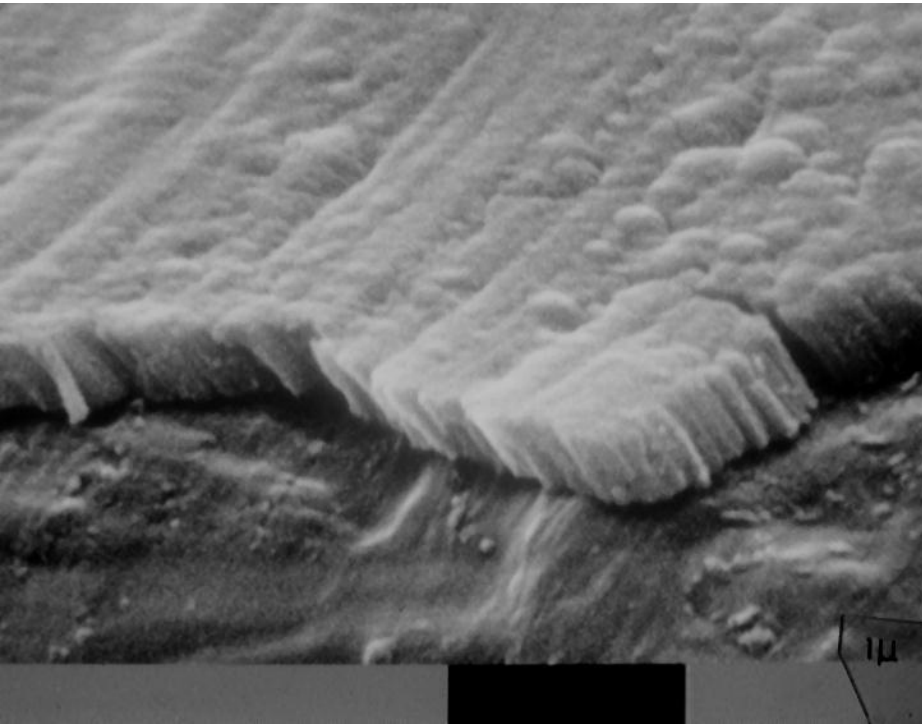
- Gas molecules are contained
  - on the NEG coating surface
    - after exposure to air
      - minimise exposure to air
  - inside the NEG coating
    - trapped during deposition
      - purity of discharge gas
      - background pressure
  - in subsurface substrate layer
    - substrate bakeout before NEG deposition
  - in the substrate bulk
    - vacuum firing



# SEM images of films (film morphology )

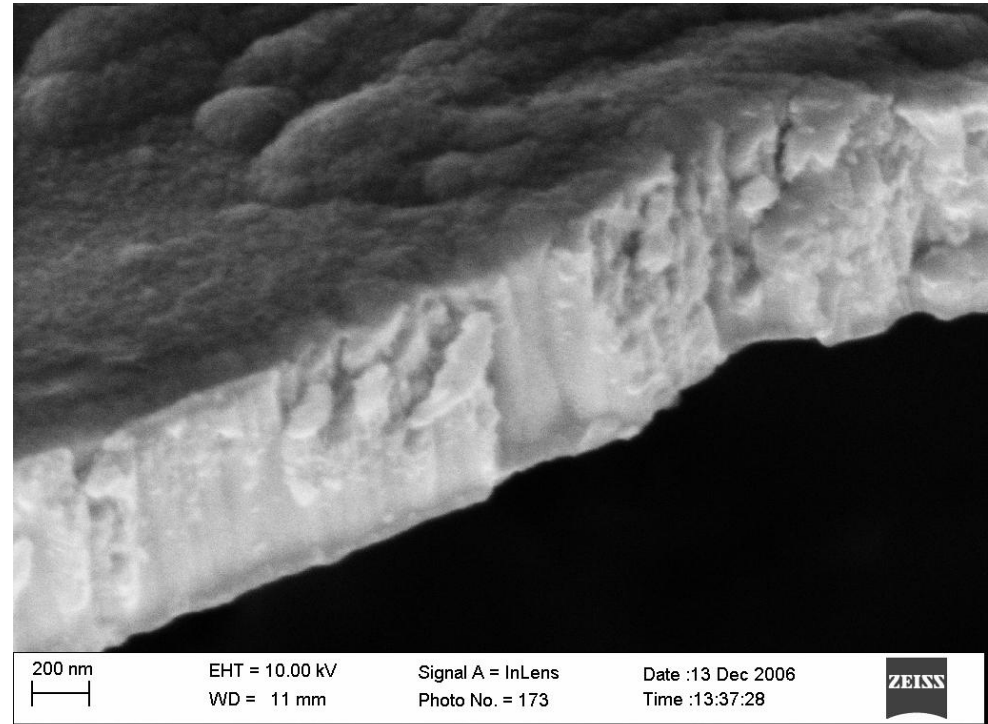
columnar

Best for pumping



dense

A first candidate for a barrier



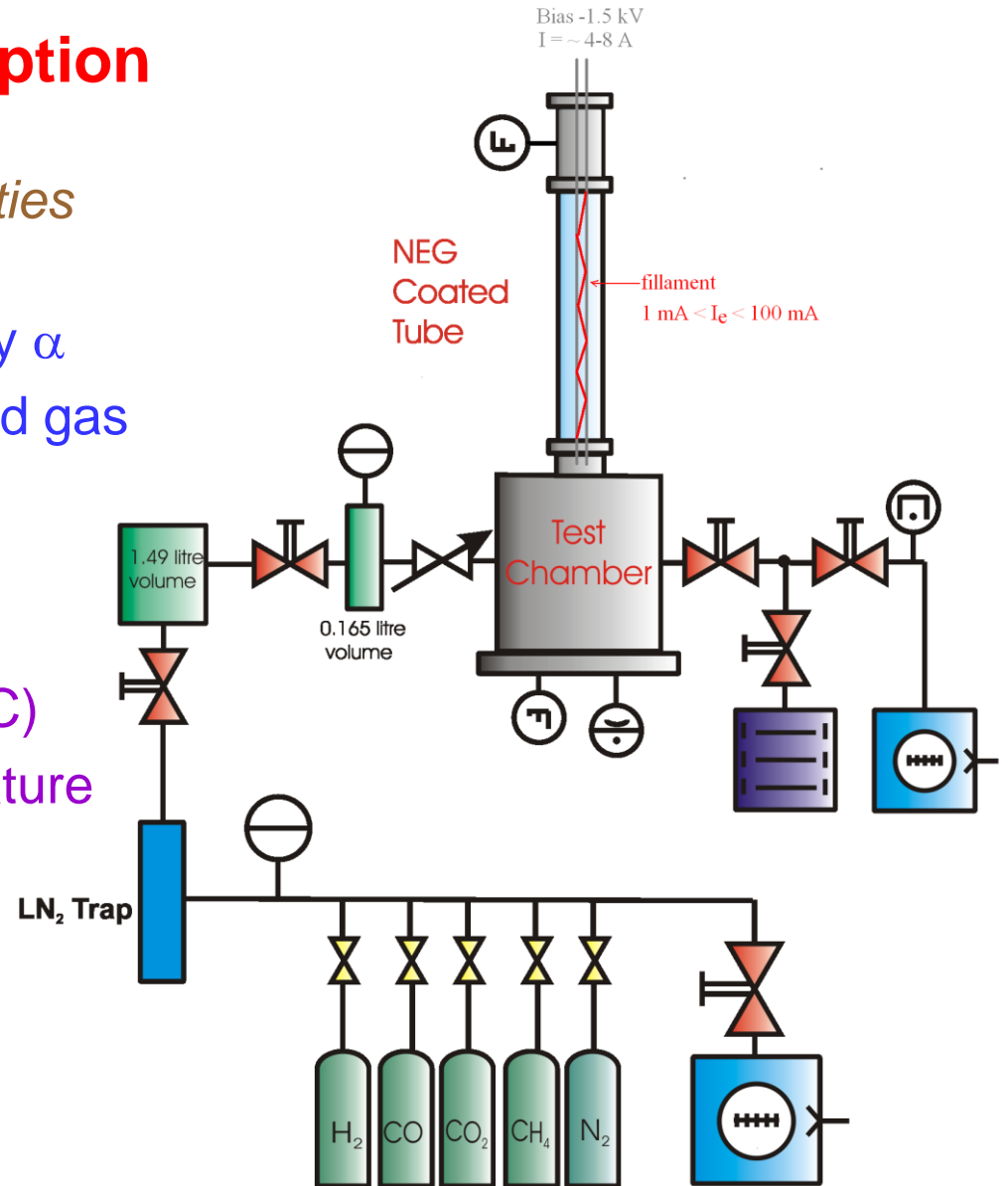
O.B. Malyshev, R. Valizadeh, J.S. Colligon *et al.* J. Vac. Sci. Technol. A 27 (2009), p. 521.



# Electron stimulated desorption

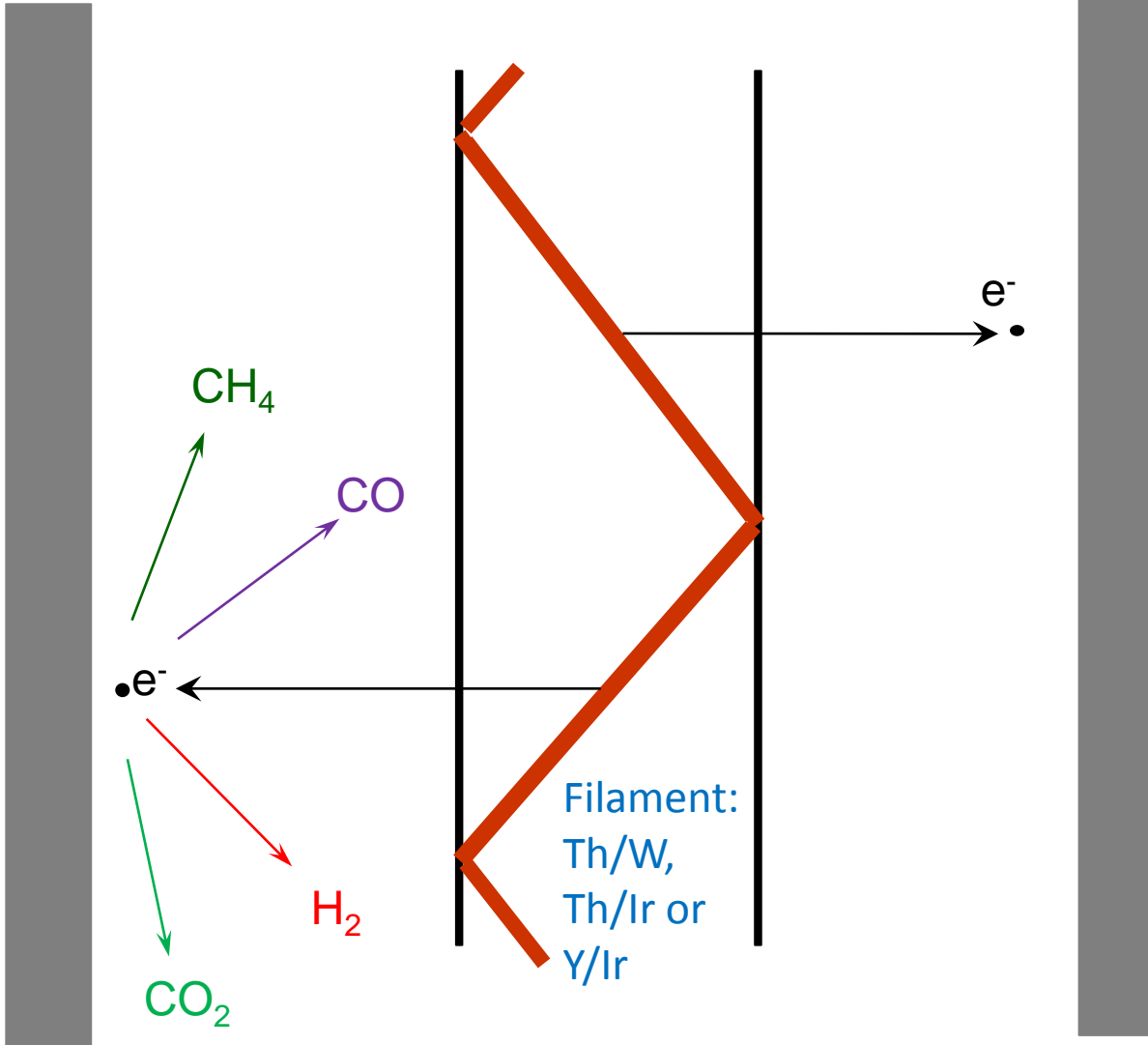
*Modified NEG pumping properties evaluation rig:*

- To measure sticking probability  $\alpha$
- To measure electron stimulated gas desorption as a function of
  - Electron energy
  - Dose
  - Wall temperature (20-100°C)
  - Activation/bakeout temperature
- Can be used for samples with:
  - NEG coating
  - Low desorption coating
  - No coatings





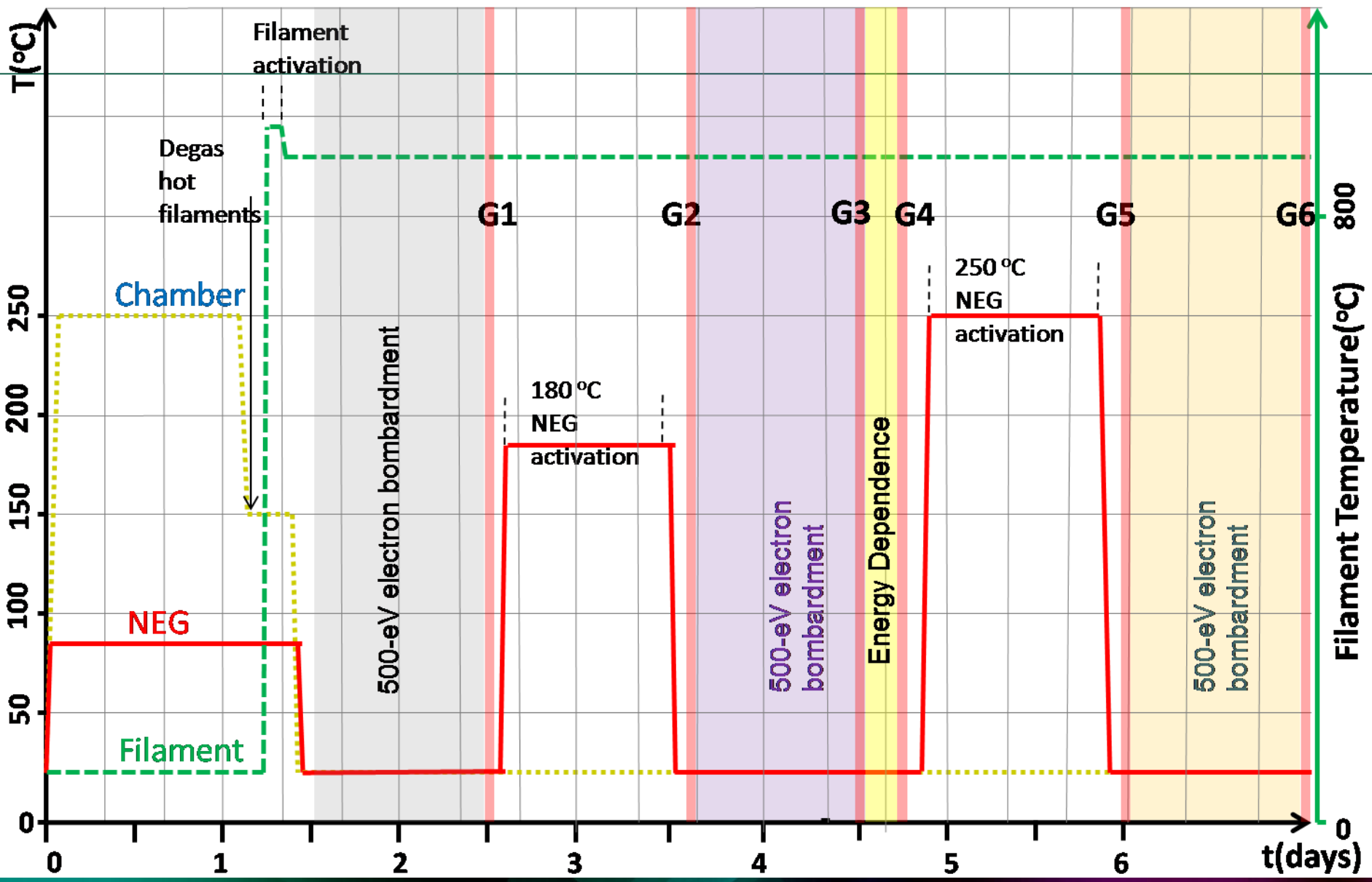
# Electron Bombardment



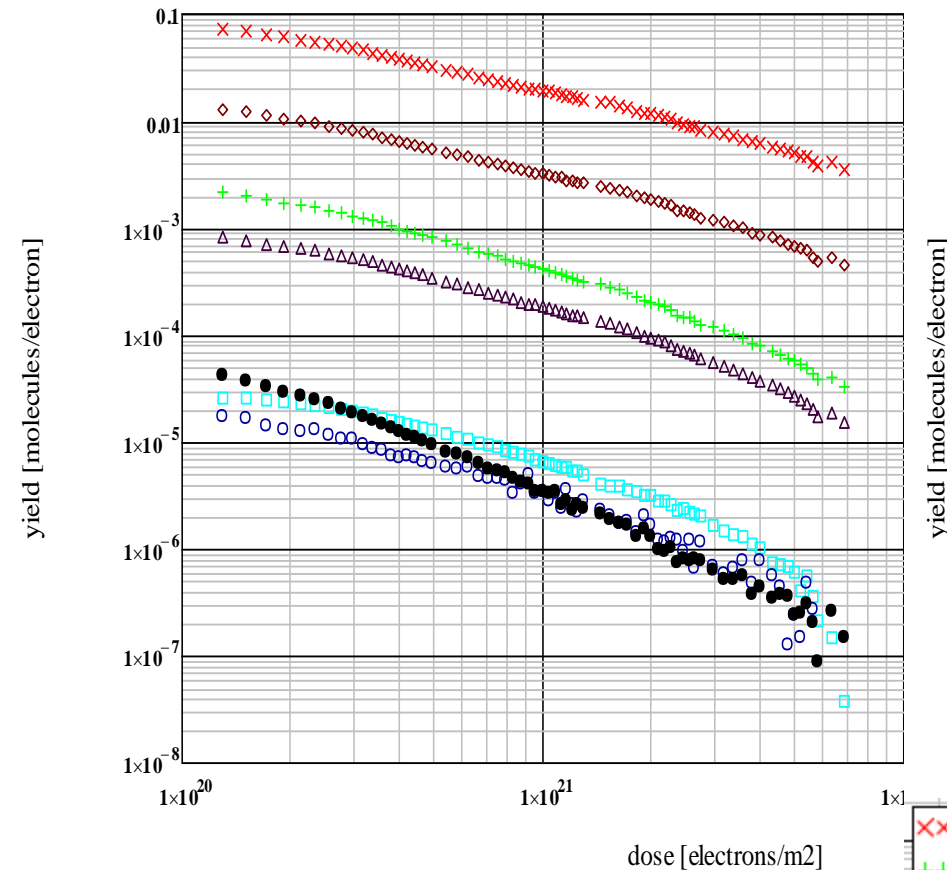
## ***Electron Stimulated Desorption (ESD) studies programme***

- ESD as a function of
  - Activation/bakeout temperature
  - Electron energy
  - Electron dose
  - Coating density, morphology and structure
  - Deposition conditions
  - Substrate

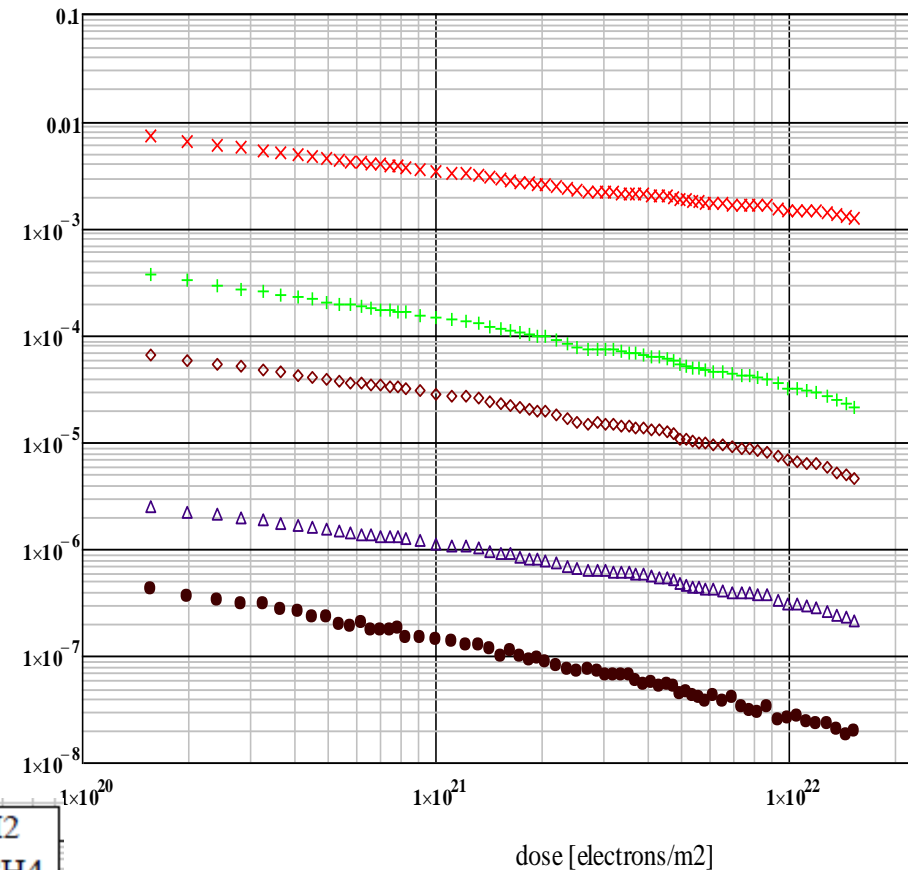
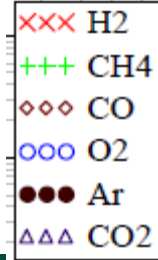
# Experimental procedure for NEG coated samples



# ESD: stainless steel vs non-activated NEG coated vacuum chamber

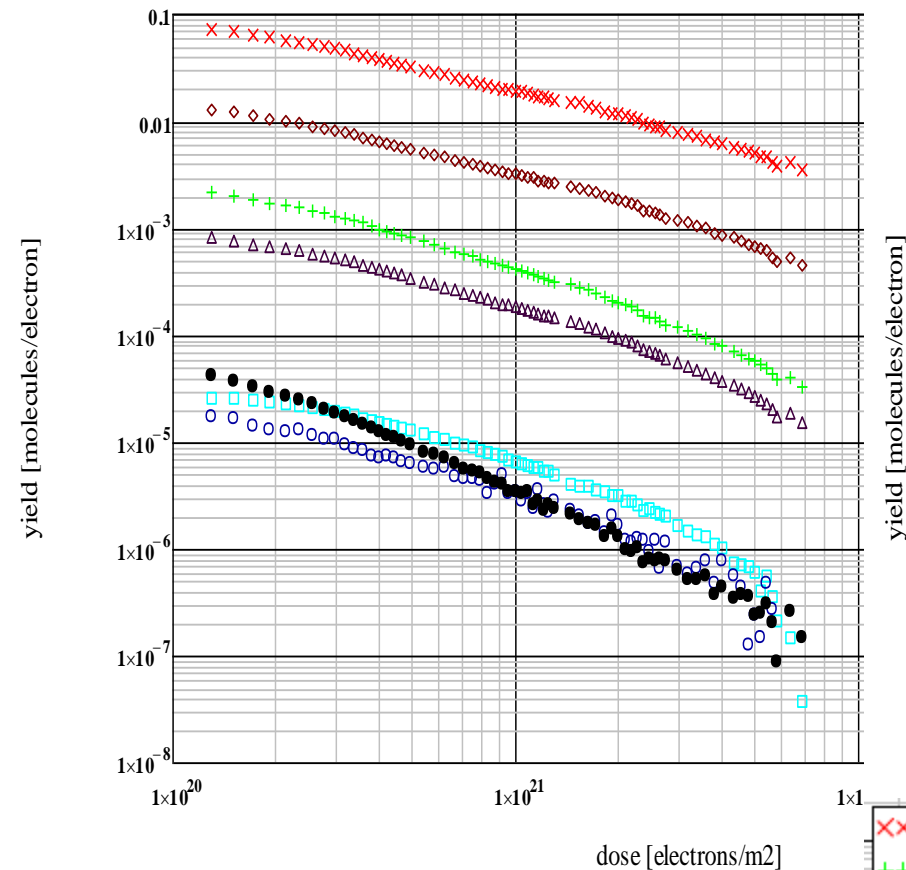


Baked to 250°C for 24 hrs  
Pumped for 30 days

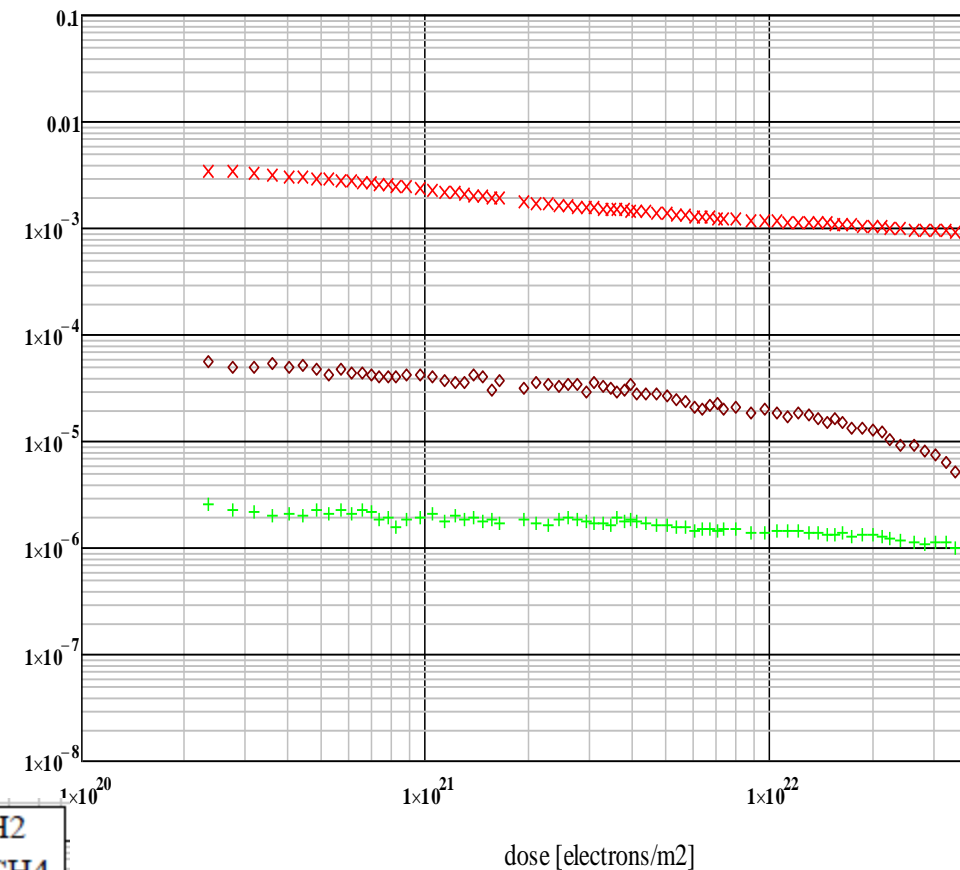
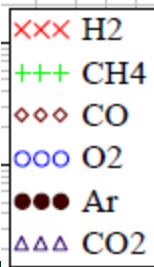


Baked to 80°C for 24 hrs  
pumped for 1 day

# ESD: stainless steel vs activated NEG coated vacuum chamber

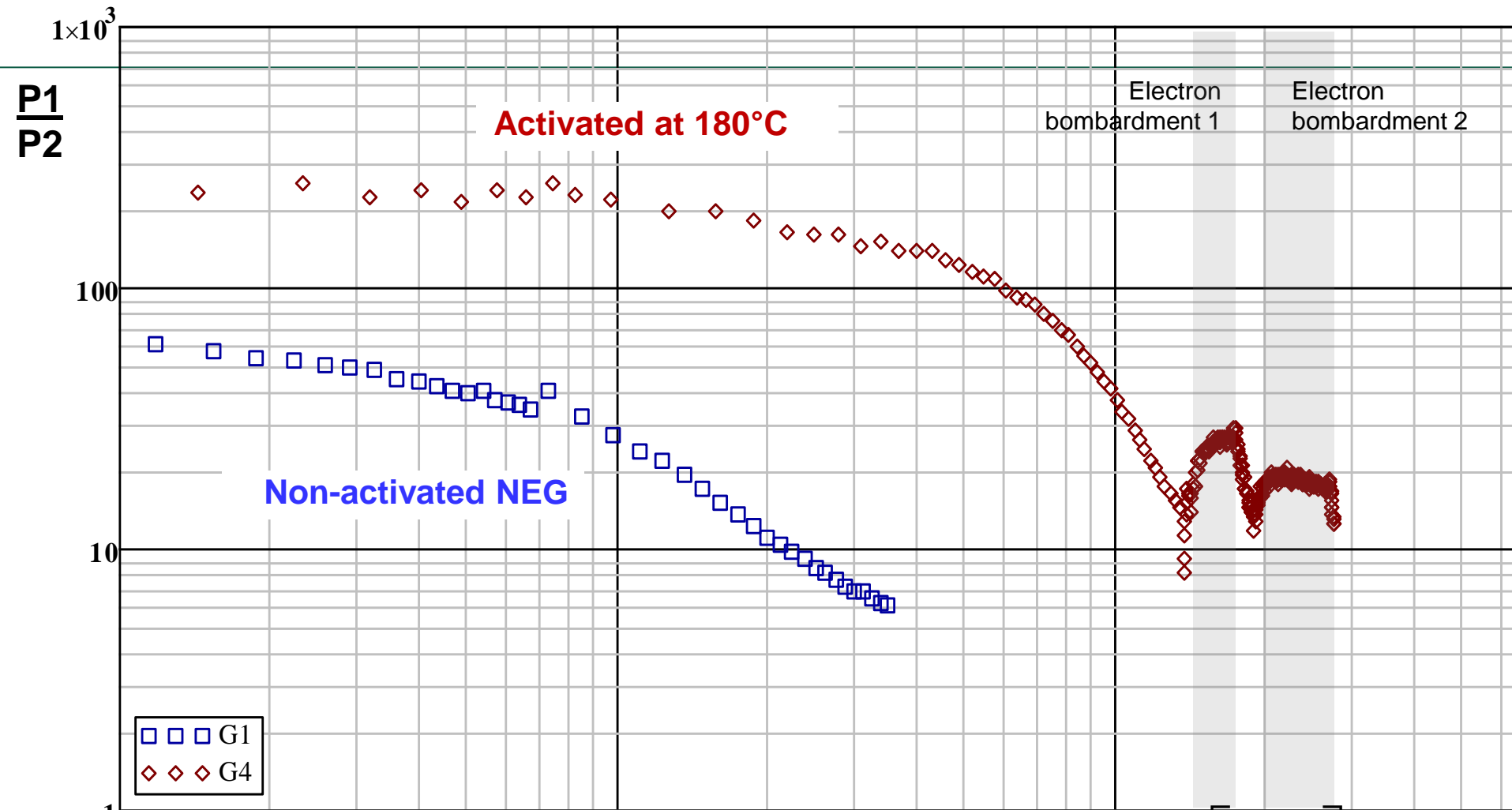


Baked to 250°C for 24 hrs



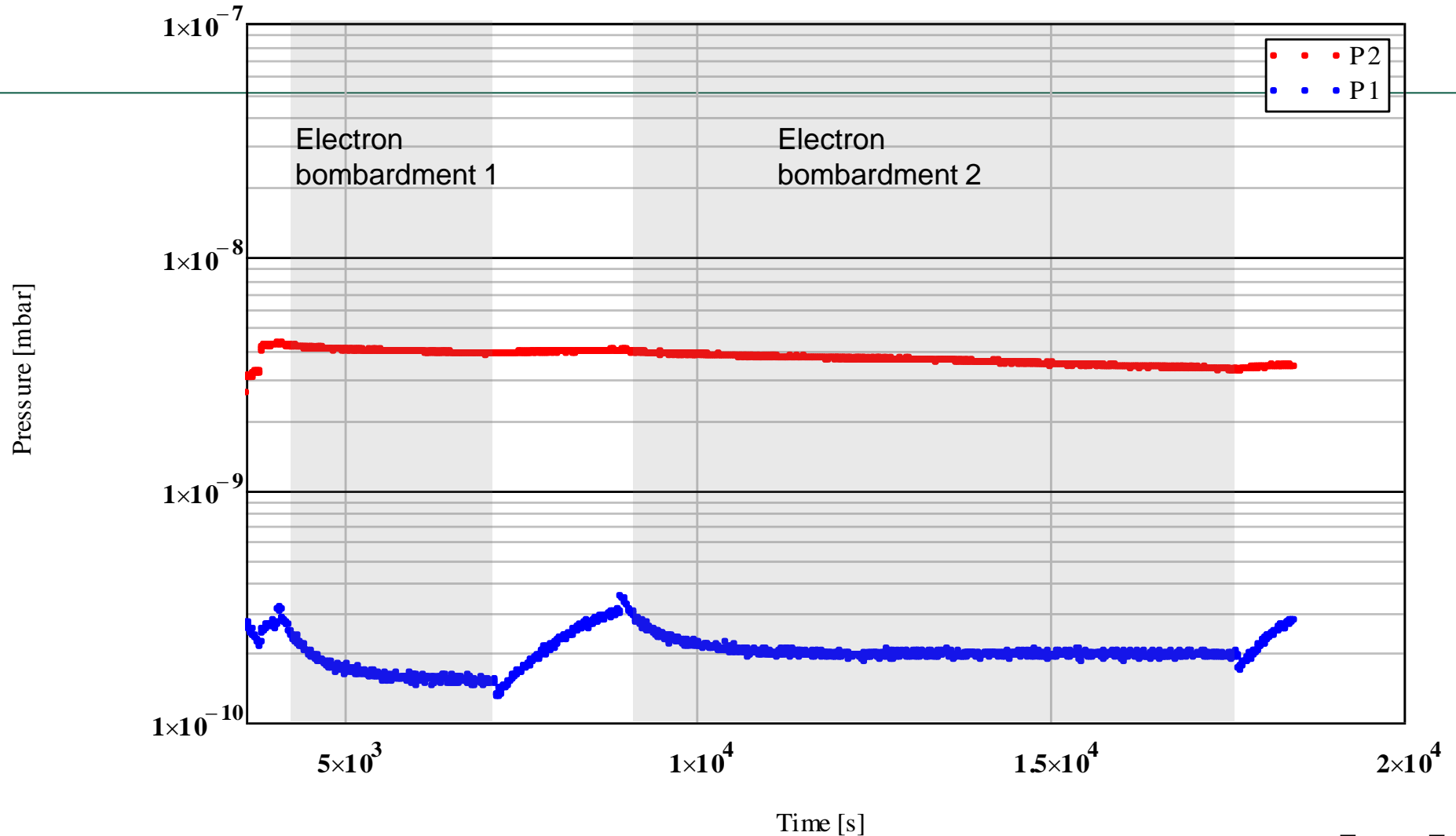
Activated to 180°C for 24 hrs

*O.B. Malyshev, A. Smith, R. Valizadeh, A. Hannah.  
Accepted by J. Vac. Sci. Technol., Aug. 2010.*



The electron stimulated NEG activation efficiency estimated as  $7.9 \times 10^{-4} < \sigma_1 < 2.4 \times 10^{-3} \text{ [CO/e}^-]$

$$\sigma_1 \left[ \frac{\text{CO}}{e^-} \right] = \frac{\Omega_{\text{CO}}}{D}$$

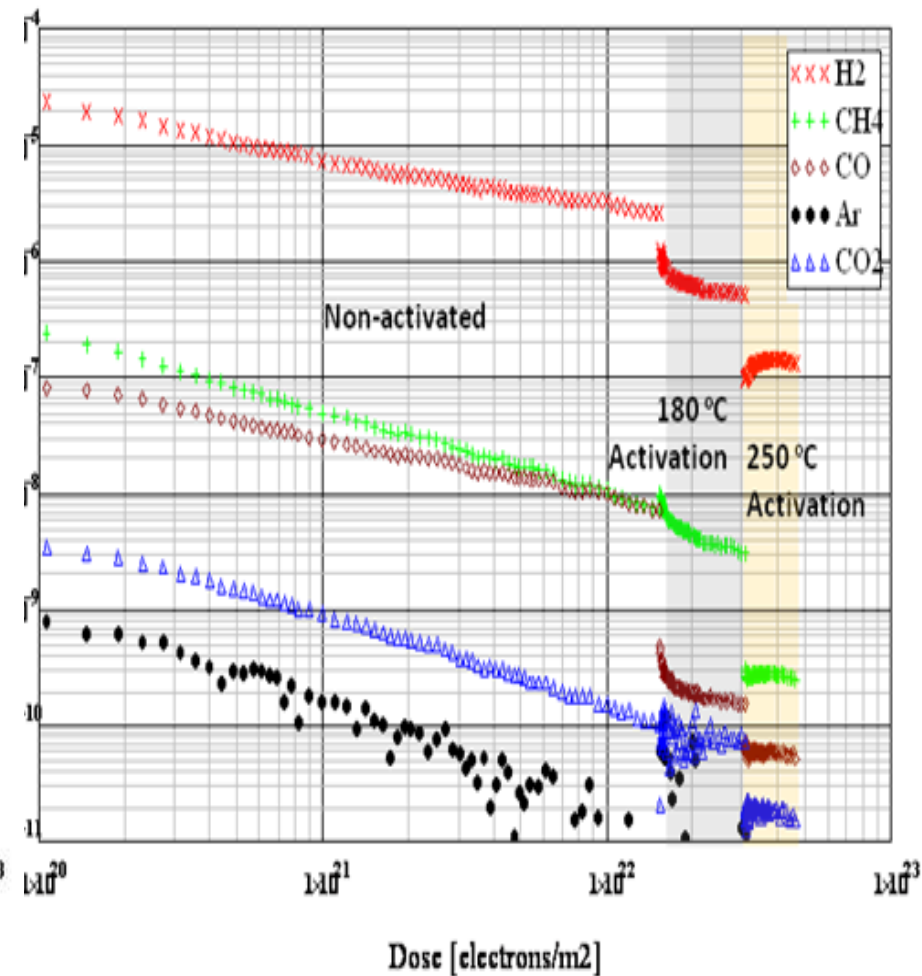
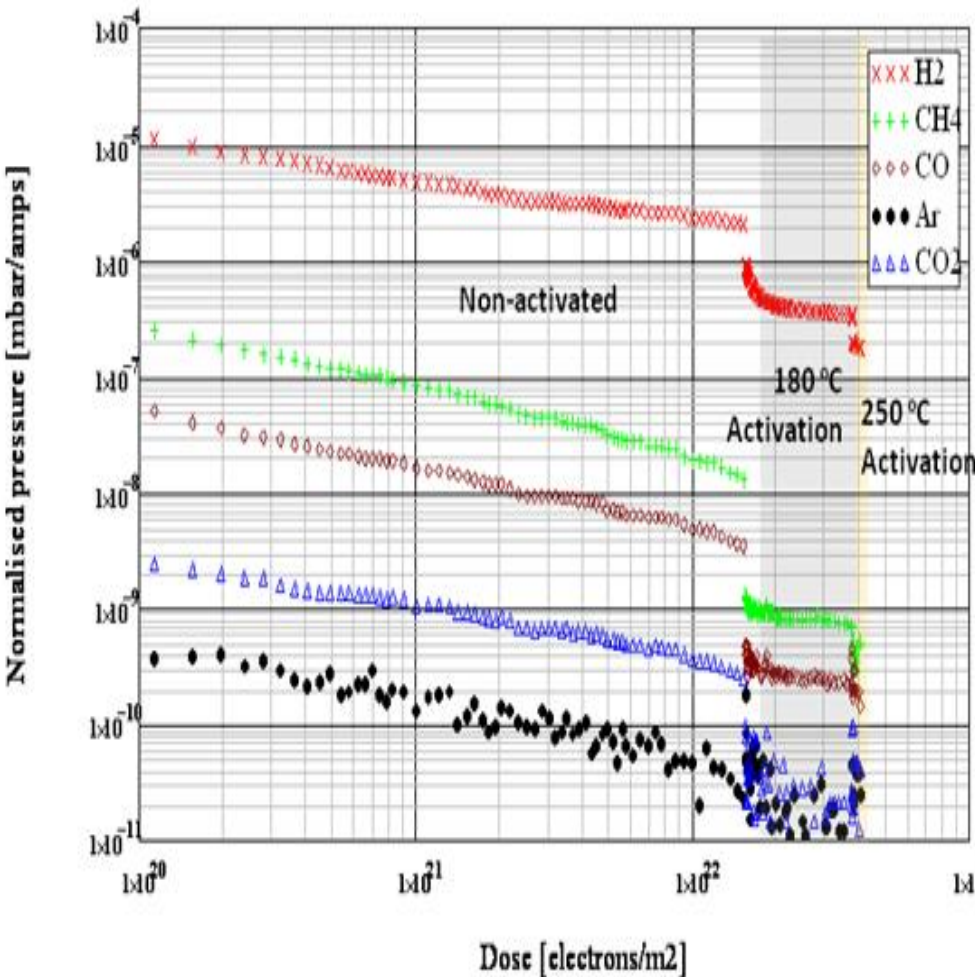


The electron stimulated NEG activation efficiency estimated as

$$\sigma_2 = \frac{Q_{CO}}{k_B T} \frac{q_e}{I} = 2.2 \times 10^{-3} \left[ \frac{CO}{e^-} \right]$$



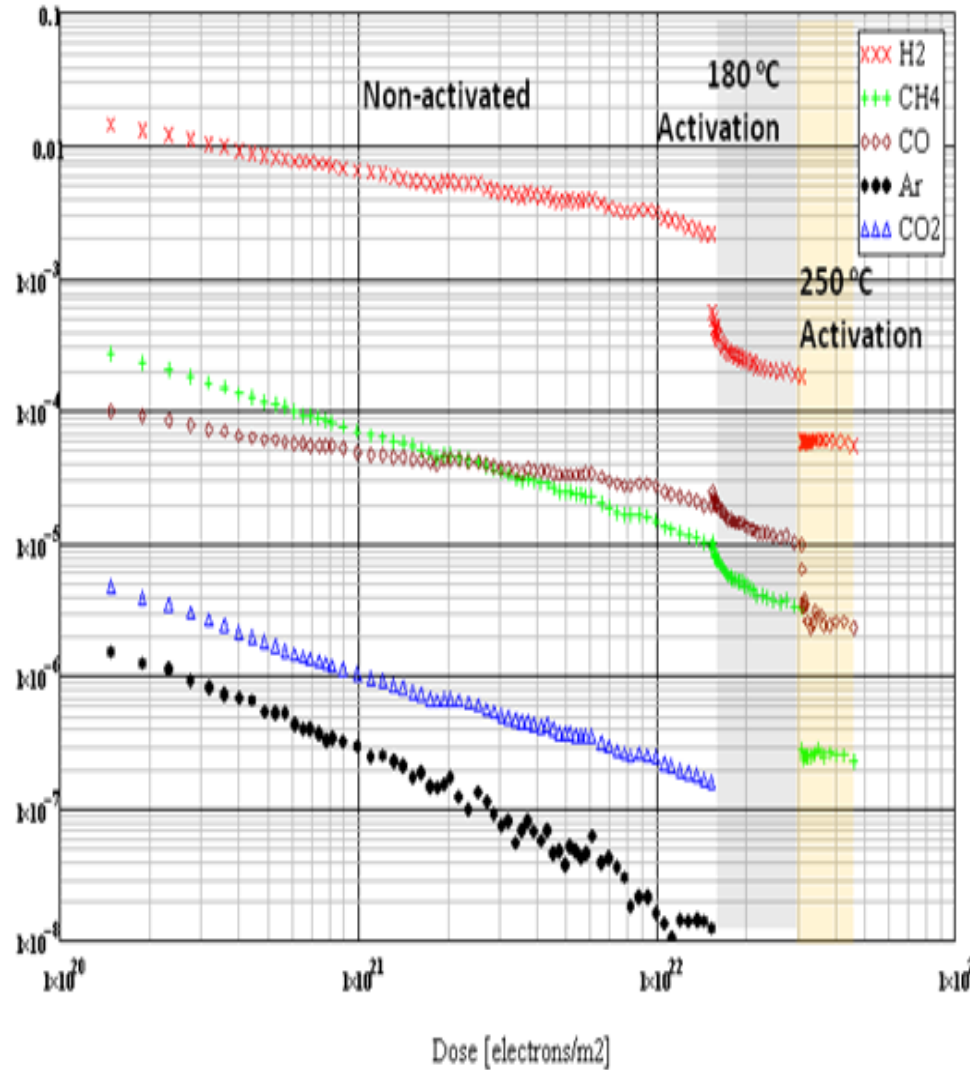
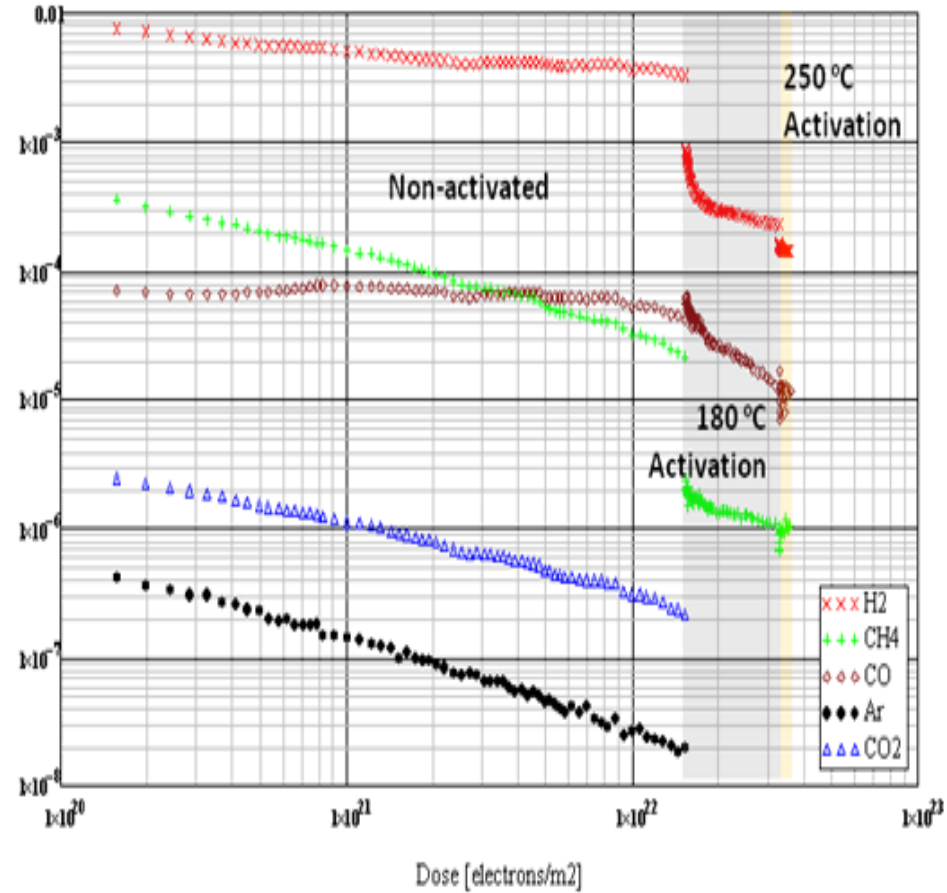
# Normalised pressure P1 Columnar vs. Dense



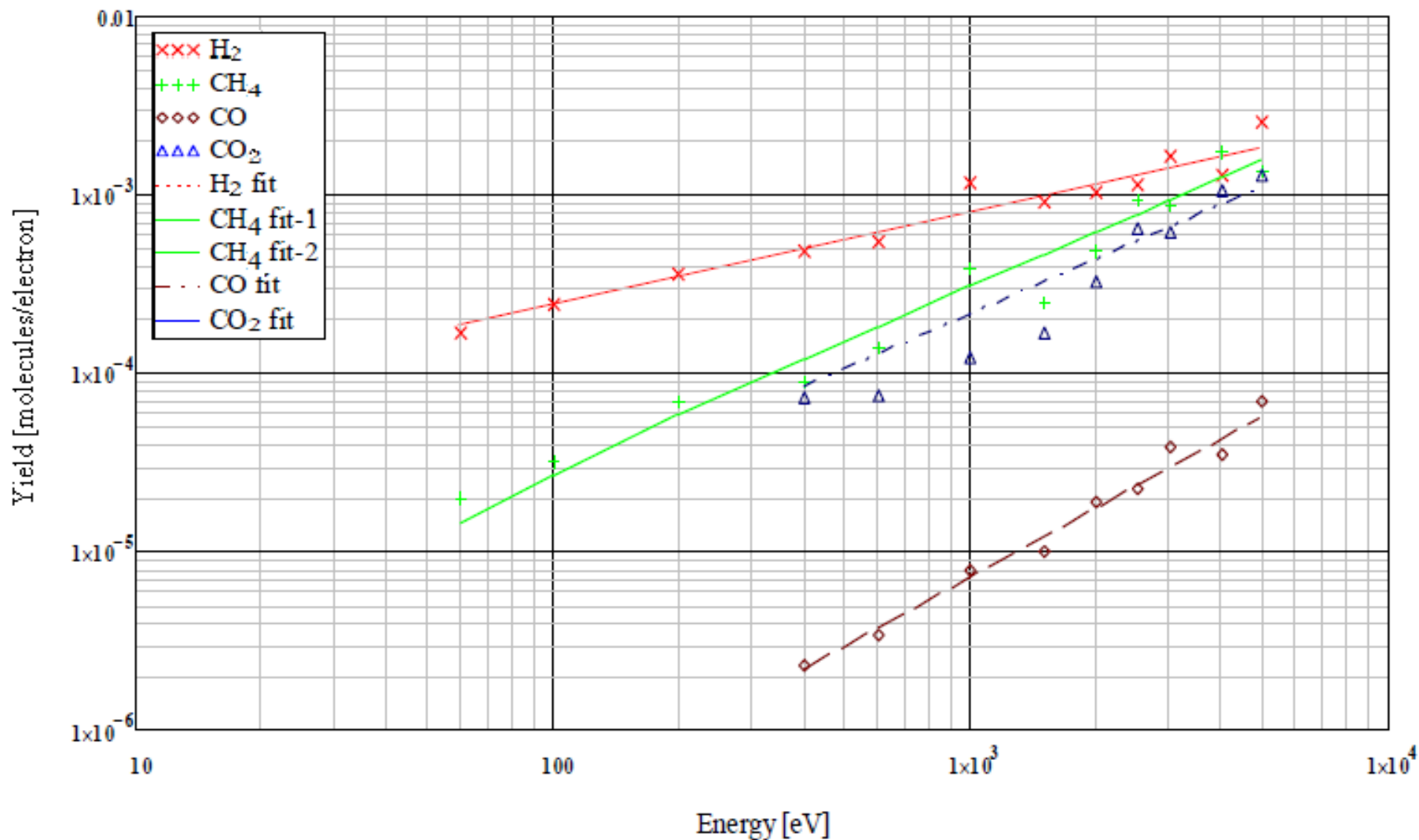
$$\alpha_c(\text{H}_2) = 1.5 \alpha_d(\text{H}_2); \alpha_c(\text{CO}) = 1.5 \alpha_d(\text{CO})$$

# ESD Yields

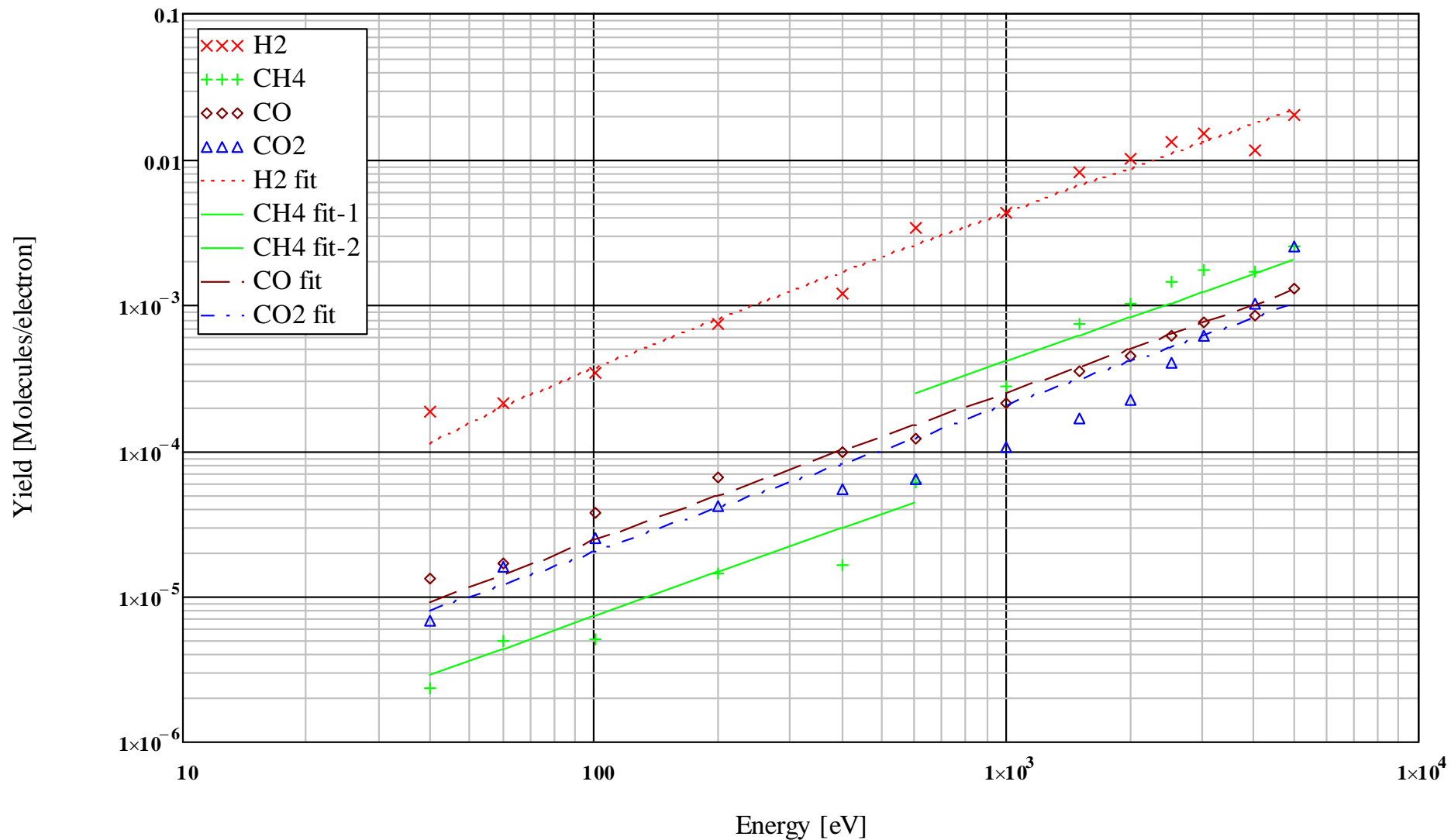
## Columnar vs. Dense



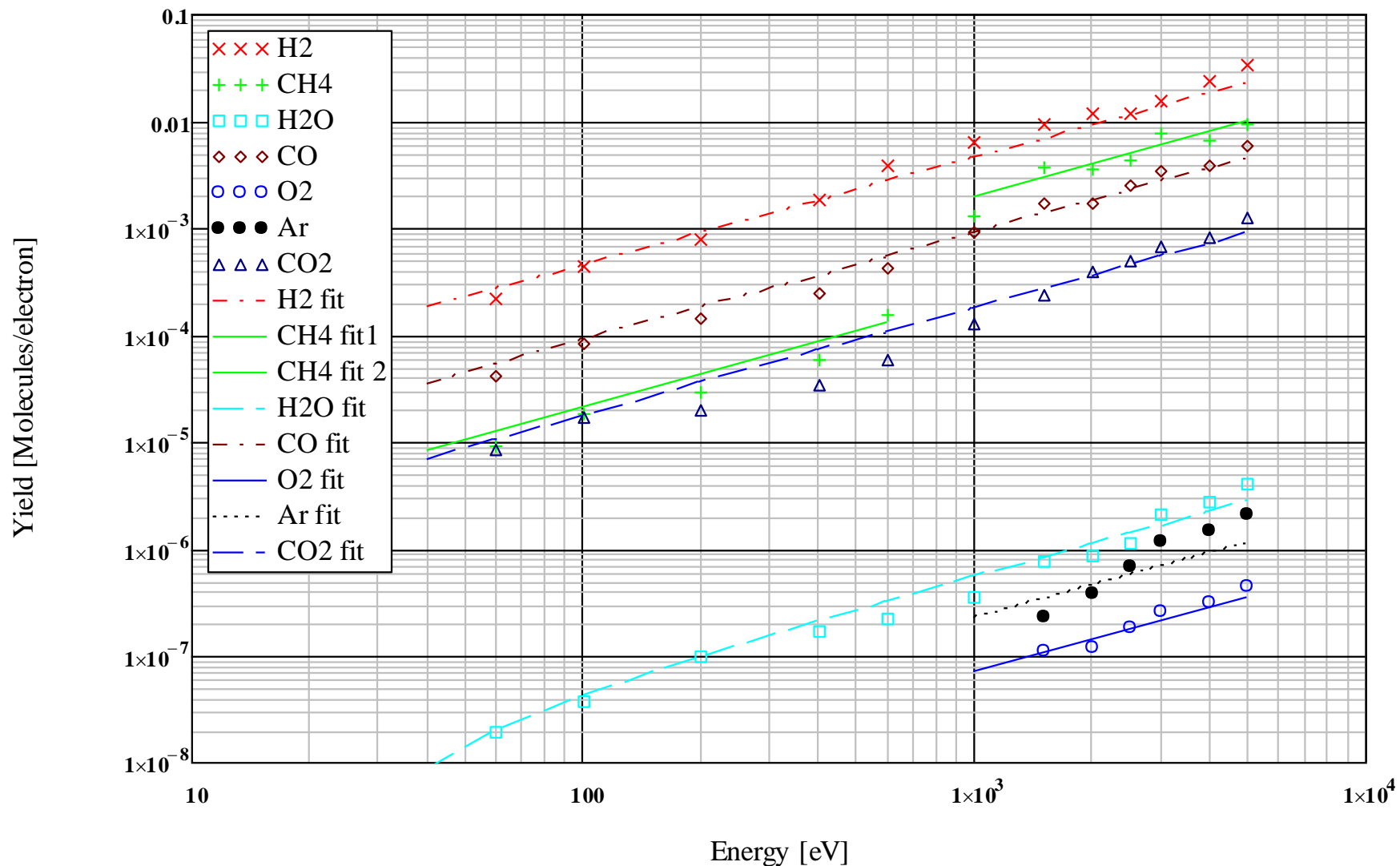
# $\eta(E_e)$ for different gases for NEG coating



# $\eta(E_{e^-})$ for different gases for 316LN



# $\eta(E_{e^-})$ for different gases for aluminium alloy



## Conclusions:

- ASTeC activation procedure minimises NEG poisoning from non-coated vacuum chamber components
- Role of element:
  - Zr-based – highest sticking probability and capacity, lowers activation temp.
  - Ti-based – lowest sticking probability and capacity, highest activation temp
- Role of grain size
  - Activation temperature reduces with a grain size die to increase the grain boundary density
- Quaternary alloy demonstrated the lowest activation temperature and best pumping properties;
  - Pure Zr film is good as well
- Alloy target is better than twisted wires
- The improvement and further development of NEG coatings requires
  - Intensive use surface analysis techniques
  - Evaluation under photon, electron and ion bombardment.



## Conclusions (2):

- An ESD set-up for tubular sample
  - Uniform bombardment along the tube
  - From both pumping and non-pumping samples.
- The ESD yields as a function of electron dose :
  - 316L stainless steel sample after bakeout at 250°C
  - Ti-Zr-V coated before NEG activation and after activation at 180°C and 250 °C.
  - Desorption yields from SS are comparable with earlier results from literature;
  - The initial desorption yields from NEG coating are 20 times lower for H<sub>2</sub>, 1000 times lower for CH<sub>4</sub> and 200 times lower for CO, the desorption yields for other gases below the installation sensitivity.
- The ESD yields as a function of electron energy:
  - were measured in the energy range between 40 eV and 5 keV.
  - a linear dependence was measured for most of gases
  - except for H<sub>2</sub>, for which the dependence is:  $\eta(E) \propto E^{2/3}$
- The electron bombardment induced pumping of the CO saturated NEG film was observed for a first time
  - this effect is similar to photon induced pumping of the NEG film observed earlier.



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## Co-authors (team):

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- Dr. V. Vishnyakov

